

FLASH MEMORY

CMOS

8M (1M × 8) BIT

MBM29LV080A-70/-90/-12

■ FEATURES

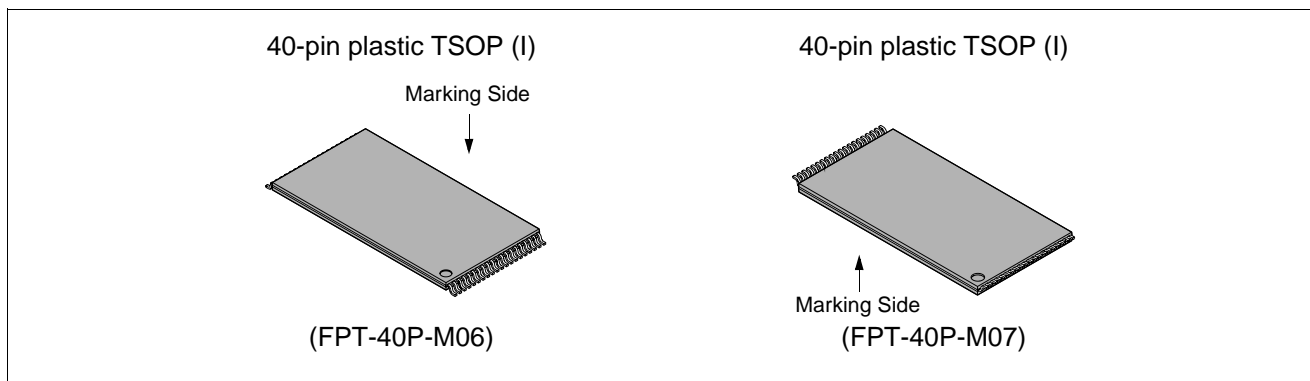
- **Address specification is not necessary during command sequence**
- **Single 3.0 V read, program and erase**
Minimizes system level power requirements
- **Compatible with JEDEC-standard commands**
Uses same software commands as E²PROMs
- **Compatible with JEDEC-standard world-wide pinouts**
40-pin TSOP (I) (Package suffix: PTN-Normal Bend Type, PTR-Reversed Bend Type)
- **Minimum 100,000 program/erase cycles**

(Continued)

■ PRODUCT LINE UP

Part No.		MBM29LV080A		
Ordering Part No.	V _{CC} = 3.3 V ^{+0.3 V} / _{-0.3 V}	-70	—	—
	V _{CC} = 3.0 V ^{+0.6 V} / _{-0.3 V}	—	-90	-12
Max. Address Access Time (ns)		70	90	120
Max. \overline{CE} Access Time (ns)		70	90	120
Max. \overline{OE} Access Time (ns)		30	35	50

■ PACKAGE



(Continued)

- **High performance**
70 ns maximum access time
- **Sector erase architecture**
16 sectors of 64K bytes each
Any combination of sectors can be concurrently erased. Also supports full chip erase
- **Embedded Erase™* Algorithms**
Automatically pre-programs and erases the chip or any sector
- **Embedded program™* Algorithms**
Automatically programs and verifies data at specified address
- **Data Polling and Toggle Bit feature for detection of program or erase cycle completion**
- **Ready/Busy output (RY/BY)**
Hardware method for detection of program or erase cycle completion
- **Automatic sleep mode**
When addresses remain stable, automatically switches themselves to low power mode
- **Low V_{CC} write inhibit ≤ 2.5 V**
- **Hardware RESET pin**
Resets internal state machine to the read mode
- **Erase Suspend/Resume**
Suspends the erase operation to allow a read data and/or program in another sector within the same device
- **Sector protection**
Hardware method disables any combination of sectors from program or erase operations
- **Sector Protection set function by Extended sector protect command**
- **Temporary sector unprotection**
Temporary sector unprotection via the RESET pin

* : Embedded Erase™ and Embedded Program™ are trademarks of Advanced Micro Devices, Inc.

■ GENERAL DESCRIPTION

The MBM29LV080A is a 16M-bit, 3.0 V-only Flash memory organized as 1M bytes of 8 bits each. The 1M bytes of data is divided into 32 sectors of 64K bytes of flexible erase capability. The 8 bits of data will appear on DQ₀ to DQ₇. The MBM29LV080A is offered in a 40-pin TSOP (I) package. The device is designed to be programmed in-system with the standard system 3.0 V V_{CC} supply. 12.0 V V_{PP} and 5.0 V V_{CC} are not required for write or erase operations. The device can also be reprogrammed in standard EPROM programmers.

The standard MBM29LV080A offers access times of 70 ns and 120 ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention the device has separate chip enable (\overline{CE}), write enable (\overline{WE}), and output enable (\overline{OE}) controls.

The MBM29LV080A is pin and command set compatible with JEDEC standard E²PROMs. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the device is similar to reading from 5.0 V and 12.0 V Flash or EPROM devices.

The MBM29LV080A is programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margins. Typically, each sector can be programmed and verified in about 0.5 seconds. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margins.

Any individual sector is typically erased and verified in 1.0 second. (If already preprogrammed.)

The device also features a sector erase architecture. The sector mode allows each sector to be erased and reprogrammed without affecting other sectors. The MBM29LV080A is erased when shipped from the factory.

Fujitsu has implemented an Erase Suspend feature that enables the user to put erase on hold for any period of time to read data from or program data to a mom-busy sector. Thus, true background erase can be achieved.

The device features single 3.0 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. A low V_{CC} detector automatically inhibits write operations on the loss of power. The end of program or erase is detected by \overline{Data} Polling of DQ₇, by the Toggle Bit feature on DQ₆, or the RY/ \overline{BY} output pin. Once the end of a program or erase cycle has been completed, the device internally resets to the read mode.

The MBM29LV080A also has a hardware \overline{RESET} pin. When this pin is driven low, execution of any Embedded Program Algorithm or Embedded Erase Algorithm is terminated. The internal state machine is then reset to the read mode. The \overline{RESET} pin may be tied to the system reset circuitry. Therefore, if a system reset occurs during the Embedded Program Algorithm or Embedded Erase Algorithm, the device is automatically reset to the read mode and will have erroneous data stored in the address locations being programmed or erased. These locations need re-writing after the Reset. Resetting the device enables the system's microprocessor to read the boot-up firmware from the Flash memory.

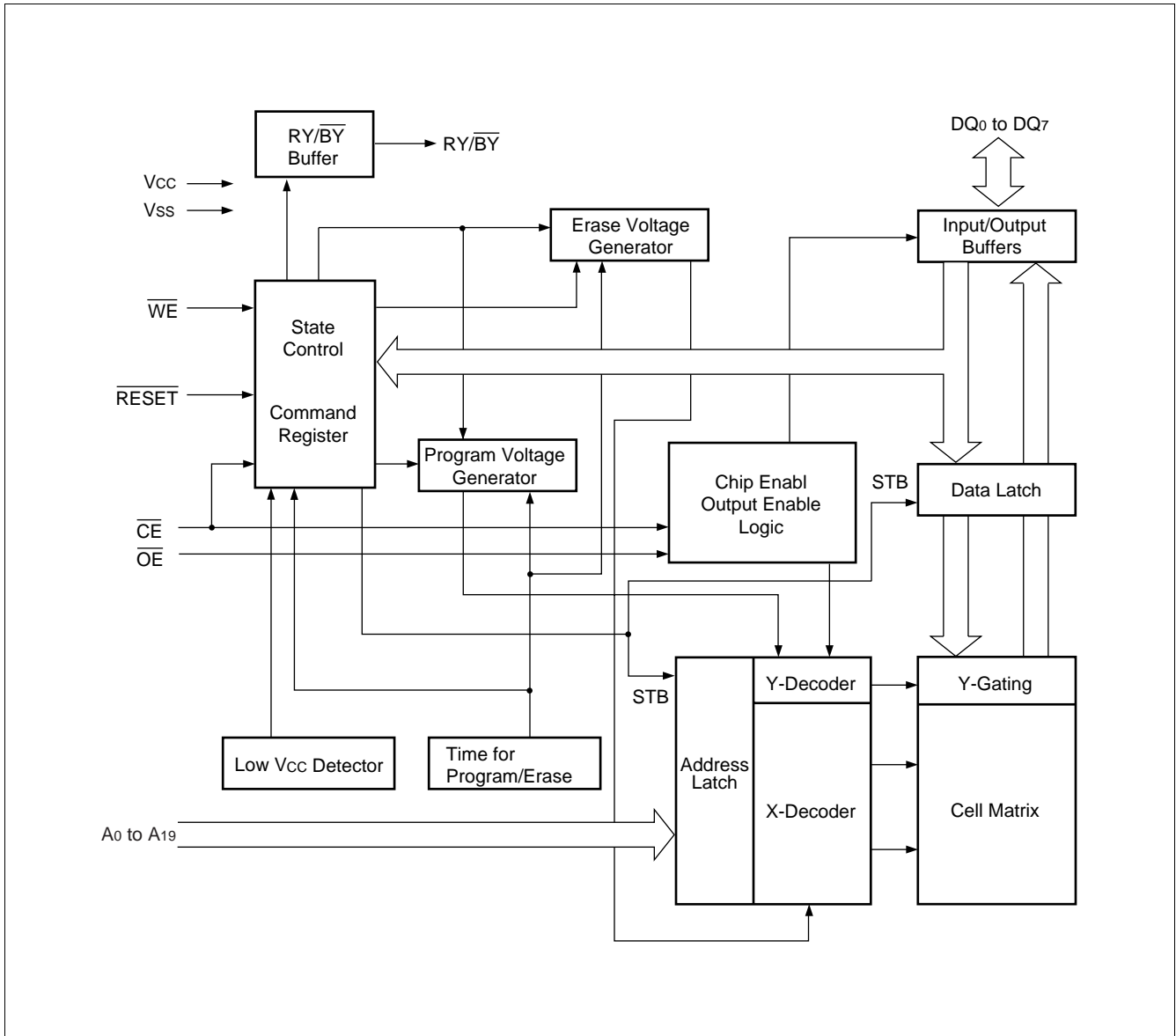
Fujitsu's Flash technology combines years of Flash memory manufacturing experience to produce the highest levels of quality, reliability, and cost effectiveness. The MBM29LV080A memory electrically erases all bits within a sector simultaneously via Fowler-Nordhiem tunneling. The bytes are programmed one byte at a time using the EPROM programming mechanism of hot electron injection.

■ FLEXIBLE SECTOR-ERASE ARCHITECTURE

- Sixteen 64K byte sectors
- Loading the sector erase buffer may be done in any sequence and with any number of sectors (0 to 15).
- Individual-sector or multiple-sector erase capability
- Sector protection is user-definable.

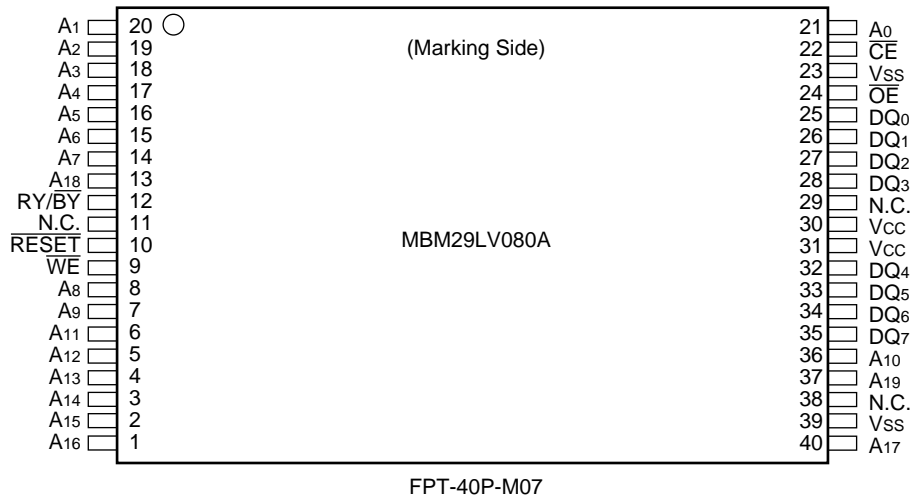
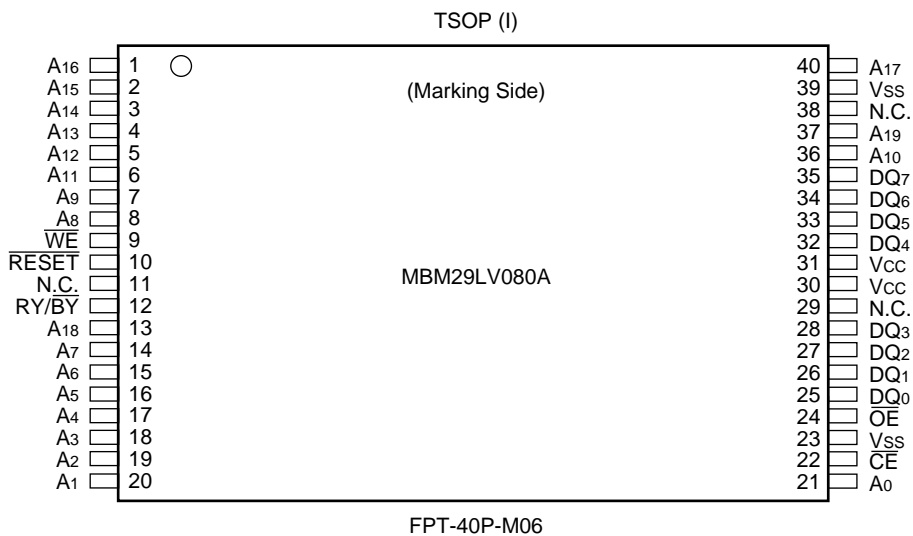
64 Kbytes	FFFFFFH
64 Kbytes	EFFFFFFH
64 Kbytes	DFFFFFFH
64 Kbytes	CFFFFFFH
64 Kbytes	BFFFFFFH
64 Kbytes	AFFFFFFH
64 Kbytes	9FFFFFFH
64 Kbytes	8FFFFFFH
64 Kbytes	7FFFFFFH
64 Kbytes	6FFFFFFH
64 Kbytes	5FFFFFFH
64 Kbytes	4FFFFFFH
64 Kbytes	3FFFFFFH
64 Kbytes	2FFFFFFH
64 Kbytes	1FFFFFFH
64 Kbytes	0FFFFFFH
64 Kbytes	00000H

■ BLOCK DIAGRAM



MBM29LV080A-70/-90/-12

CONNECTION DIAGRAMS



LOGIC SYMBOL

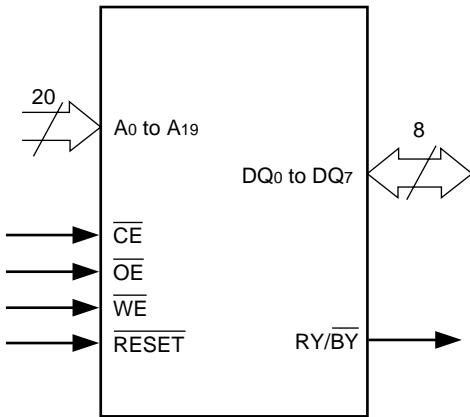


Table 1 MBM29LV080A Pin Configuration

Pin	Function
A ₀ to A ₁₉	Address Inputs
DQ ₀ to DQ ₇	Data Inputs/Outputs
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
RY/ \overline{BY}	Ready/Busy Output
\overline{RESET}	Hardware Reset Pin/ Temporary Sector Unprotection
N.C.	Pin Not Connected Internally
V _{SS}	Device Ground
V _{CC}	Device Power Supply

Table 2 MBM29LV080A User Bus Operation

Operation	\overline{CE}	\overline{OE}	\overline{WE}	A ₀	A ₁	A ₆	A ₉	A ₁₀	DQ ₀ to DQ ₇	\overline{RESET}
Auto-Select Manufacture Code (1)	L	L	H	L	L	L	V _{ID}	L	Code	H
Auto-Select Device Code (1)	L	L	H	H	L	L	V _{ID}	L	Code	H
Read (2)	L	L	H	A ₀	A ₁	A ₆	A ₉	A ₁₀	D _{OUT}	H
Standby	H	X	X	X	X	X	X	X	HIGH-Z	H
Output Disable	L	H	H	X	X	X	X	X	HIGH-Z	H
Write (Program/Erase)	L	H	L	A ₀	A ₁	A ₆	A ₉	A ₁₀	D _{IN}	H
Enable Sector Protection (3), (4)	L	V _{ID}	$\overline{\square}$	L	H	L	V _{ID}	X	X	H
Verify Sector Protection (3), (4)	L	L	H	L	H	L	V _{ID}	L	Code	H
Temporary Sector Unprotection (5)	X	X	X	X	X	X	X	X	X	V _{ID}
Reset (Hardware)/Standby	X	X	X	X	X	X	X	X	HIGH-Z	L

Legend: L = V_{IL}, H = V_{IH}, X = V_{IL} or V_{IH}. $\overline{\square}$ = pulse input. See DC Characteristics for voltage levels.

Notes: 1. Manufacturer and device codes may also be accessed via a command register write sequence. See Table 6.

2. \overline{WE} can be V_{IL} if \overline{OE} is V_{IL}, \overline{OE} at V_{IH} initiates the write operations.

3. Refer to the section on Sector Protection.

4. V_{CC} = 3.3 V ±10%

5. It is also used for the extended sector protection.

■ FUNCTIONAL DESCRIPTION

Read Mode

The MBM29LV080A has two control functions which must be satisfied in order to obtain data at the outputs. \overline{CE} is the power control and should be used for a device selection. \overline{OE} is the output control and should be used to gate data to the output pins if a device is selected.

Address access time (t_{ACC}) is equal to the delay from stable addresses to valid output data. The chip enable access time (t_{CE}) is the delay from stable addresses and stable \overline{CE} to valid data at the output pins. The output enable access time is the delay from the falling edge of \overline{OE} to valid data at the output pins. (Assuming the addresses have been stable for at least $t_{ACC} - t_{CE}$ time.) See Figure 5.1 for timing specifications.

Standby Mode

There are two ways to implement the standby mode on the MBM29LV080A device, one using both the \overline{CE} and \overline{RESET} pins; the other via the \overline{RESET} pin only.

When using both pins, a CMOS standby mode is achieved with \overline{CE} and \overline{RESET} inputs both held at $V_{CC} \pm 0.3$ V. Under this condition the current consumed is less than 5 μ A max. During Embedded Algorithm operation, V_{CC} Active current (I_{CC2}) is required even $\overline{CE} = "H"$. The device can be read with standard access time (t_{CE}) from either of these standby modes.

When using the \overline{RESET} pin only, a CMOS standby mode is achieved with \overline{RESET} input held at $V_{SS} \pm 0.3$ V ($\overline{CE} = "H"$ or $"L"$). Under this condition the current is consumed is less than 5 μ A max. Once the \overline{RESET} pin is taken high, the device requires t_{RH} of wake up time before outputs are valid for read access.

In the standby mode the outputs are in the high impedance state, independent of the \overline{OE} input.

Automatic Sleep Mode

There is a function called automatic sleep mode to restrain power consumption during read-out of MBM29LV080A data.

This mode can be used effectively with an application requested low power consumption such as handy terminals.

To activate this mode, MBM29LV080A automatically switches itself to low power mode when MBM29LV080A addresses remain stably during access time of 150 ns. It is not necessary to control \overline{CE} , \overline{WE} , and \overline{OE} on the mode. Under the mode, the current consumed is typically 1 μ A (CMOS level).

Standard address access timings provide new data when addresses are changed. While in sleep mode, output data is latched and always available to the system.

Output Disable

With the \overline{OE} input at a logic high level (V_{IH}), output from the device is disabled. This will cause the output pins to be in a high impedance state.

Autoselect

The autoselect mode allows the reading out of a binary code from the device and will identify its manufacturer and type. This mode is intended for use by programming equipment for the purpose of automatically matching the device to be programmed with its corresponding programming algorithm. This mode is functional over the entire temperature range of the device.

To activate this mode, the programming equipment must force V_{ID} (11.5 V to 12.5 V) on address pin A_9 . Two identifier bytes may then be sequenced from the device outputs by toggling address A_0 from V_{IL} to V_{IH} . All addresses are DON'T CARES except A_0 , A_1 , A_6 , and A_{10} . (See Table 3.1.)

The manufacturer and device codes may also be read via the command register, for instances when the MBM29LV080A is erased or programmed in a system without access to high voltage on the A₉ pin. The command sequence is illustrated in Table 6. (Refer to Autoselect Command section.)

Byte 0 (A₀ = V_{IL}) represents the manufacturer's code (Fujitsu = 04H) and byte 1 (A₀ = V_{IH}) represents the device identifier code MBM29LV080A = 38H. All identifiers for manufacturers and device will exhibit odd parity with DQ₇ defined as the parity bit. In order to read the proper device codes when executing the autoselect, A₁ must be V_{IL}. (See Tables 3.1 and 3.2.)

In order to determine which sectors are write protected, A₁ must be at V_{IH} while running through the sector addresses; if the selected sector is protected, a logical '1' will be output on DQ₀ (DQ₀ = 1).

Table 3.1 MBM29LV080A Sector Protection Verify Autoselect Code

Type		A ₁₆ to A ₁₉	A ₁₀	A ₆	A ₁	A ₀	Code (HEX)
Manufacturer's Code		X	V _{IL}	V _{IL}	V _{IL}	V _{IL}	04H
Device Code	MBM29LV080A	X	V _{IL}	V _{IL}	V _{IL}	V _{IH}	38H
Sector Protection		Sector Addresses	V _{IL}	V _{IL}	V _{IH}	V _{IL}	01H*

*: Outputs 01H at protected sector addresses and outputs 00H at unprotected sector addresses.

Table 3.2 Expanded Autoselect Code Table

Type		Code	DQ ₇	DQ ₆	DQ ₅	DQ ₄	DQ ₃	DQ ₂	DQ ₁	DQ ₀
Manufacturer's Code		04H	0	0	0	0	0	1	0	0
Device Code	MBM29LV080A	38H	0	0	1	1	1	0	0	0
Sector Protection		01H	0	0	0	0	0	0	0	1

Table 4 Sector Address Tables

Sector Address	A ₁₉	A ₁₈	A ₁₇	A ₁₆	Address Range
SA0	0	0	0	0	00000H to 0FFFFH
SA1	0	0	0	1	10000H to 1FFFFH
SA2	0	0	1	0	20000H to 2FFFFH
SA3	0	0	1	1	30000H to 3FFFFH
SA4	0	1	0	0	40000H to 4FFFFH
SA5	0	1	0	1	50000H to 5FFFFH
SA6	0	1	1	0	60000H to 6FFFFH
SA7	0	1	1	1	70000H to 7FFFFH
SA8	1	0	0	0	80000H to 8FFFFH
SA9	1	0	0	1	90000H to 9FFFFH
SA10	1	0	1	0	A0000H to AFFFFH
SA11	1	0	1	1	B0000H to BFFFFH
SA12	1	1	0	0	C0000H to CFFFFH
SA13	1	1	0	1	D0000H to DFFFFH
SA14	1	1	1	0	E0000H to EFFFFH
SA15	1	1	1	1	F0000H to FFFFFH

Write

Device erasure and programming are accomplished via the command register. The contents of the register serve as inputs to the internal state machine. The state machine outputs dictate the function of the device.

The command register itself does not occupy any addressable memory location. The register is a latch used to store the commands, along with the address and data information needed to execute the command. The command register is written by bringing \overline{WE} to V_{IL} , while \overline{CE} is at V_{IL} and \overline{OE} is at V_{IH} . Addresses are latched on the falling edge of \overline{WE} or \overline{CE} , whichever happens later; while data is latched on the rising edge of \overline{WE} or \overline{CE} , whichever happens first. Standard microprocessor write timings are used.

Refer to AC Write Characteristics and the Erase/Programming Waveforms for specific timing parameters.

Sector Protection

The MBM29LV080A features hardware sector protection. This feature will disable both program and erase operations in any number of sectors (0 through 15). The sector protection feature is enabled using programming equipment at the user's site. The device is shipped with all sectors unprotected.

To activate this mode, the programming equipment must force V_{ID} on address pin A_9 and control pin \overline{OE} , (suggest $V_{ID} = 11.5\text{ V}$), $\overline{CE} = V_{IL}$, $A_0 = A_6 = V_{IL}$, and $A_1 = V_{IH}$. The sector addresses (A_{19} , A_{18} , A_{17} , and A_{16}) should be set to the sector to be protected. Tables 4 and 5 define the sector address for each of the sixteen (16) individual sectors. Programming of the protection circuitry begins on the falling edge of the \overline{WE} pulse and is terminated with the rising edge of the same. Sector addresses must be held constant during the \overline{WE} pulse. See figures 13 and 21 for sector protection waveforms and algorithm.

To verify programming of the protection circuitry, the programming equipment must force V_{ID} on address pin A_9 with \overline{CE} and \overline{OE} at V_{IL} and \overline{WE} at V_{IH} . Scanning the sector addresses (A_{19} , A_{18} , A_{17} , and A_{16}) while (A_{10} , A_6 , A_1 , A_0) = (0, 0, 1, 0) will produce a logical "1" code at device output DQ_0 for a protected sector. Otherwise the devices will read 00H for unprotected sector. In this mode, the lower order addresses, except for A_0 , A_1 , A_6 , and A_{10} are DON'T CARES. Address locations with $A_1 = V_{IL}$ are reserved for Autoselect manufacturer and device codes.

It is also possible to determine if a sector is protected in the system by writing an Autoselect command. Performing a read operation at the address location XX02H, where the higher order addresses (A_{19} , A_{18} , A_{17} , and A_{16}) are the sector address will produce a logical "1" at DQ_0 for a protected sector. See Tables 3.1 and 3.2 for Autoselect codes.

Temporary Sector Unprotection

This feature allows temporary unprotection of previously protected sectors of the MBM29LV080A device in order to change data. The Sector Unprotection mode is activated by setting the \overline{RESET} pin to high voltage (12 V). During this mode, formerly protected sectors can be programmed or erased by selecting the sector addresses. Once the 12 V is taken away from the \overline{RESET} pin, all the previously protected sectors will be protected again. See figure 15 and 22.

Table 5 MBM29LV080A Standard Command Definitions

Command Sequence (Notes 1, 2, 3)	Bus Write Cycles Req'd	First Bus Write Cycle		Second Bus Write Cycle		Third Bus Write Cycle		Fourth Bus Read/Write Cycle		Fifth Bus Write Cycle		Sixth Bus Write Cycle	
		Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data	Addr	Data
Read/Reset (Note 5)	1	XXXH	F0H	—	—	—	—	—	—	—	—	—	—
Read/Reset (Note 5)	3	XXXH	AAH	XXXH	55H	XXXH	F0H	RA	RD	—	—	—	—
Autoselect	3	XXXH	AAH	XXXH	55H	XXXH	90H	—	—	—	—	—	—
Byte Program (Notes 3, 4)	4	XXXH	AAH	XXXH	55H	XXXH	A0H	PA	PD	—	—	—	—
Chip Erase	6	XXXH	AAH	XXXH	55H	XXXH	80H	XXXH	AAH	XXXH	55H	XXXH	10H
Sector Erase (Note 3)	6	XXXH	AAH	XXXH	55H	XXXH	80H	XXXH	AAH	XXXH	55H	SA	30H
Sector Erase Suspend	1	XXXH	B0H										
Sector Erase Resume	1	XXXH	30H										

Notes: 1. Address bit = X = "H" or "L".

2. Bus operations are defined in Table 2.

3. RA=Address of the memory location to be read.

PA=Address of the memory location to be programmed. Addresses are latched on the falling edge of the \overline{WE} pulse.

SA=Address of the sector to be erased. The combination of A₁₉, A₁₈, A₁₇, and A₁₆ will uniquely select any sector.

4. RD=Data read from location RA during read operation.

PD=Data to be programmed at location PA. Data is latched on the rising edge of \overline{WE} .

5. Both Read/Reset commands are functionally equivalent, resetting the device to the read mode.

Command Definitions

Device operations are selected by writing specific address and data sequences into the command register. Writing incorrect address and data values or writing them in the improper sequence will reset the devices to read mode. Table 6 defines the valid register command sequences. Note that the Erase Suspend (B0H) and Erase Resume (30H) commands are valid only while the sector Erase operation is in progress. Moreover, both Read/Reset commands are functionally equivalent, resetting the device to the read mode. Please note that commands are always written at DQ₀ to DQ₇ bits are ignored.

Table 6 MBM29LV080A Extended Command Definitions

Command Sequence	Bus Write Cycles Req'd	First Bus Write Cycle		Second Bus Write Cycle		Third Bus Write Cycle		Fourth Bus Read Cycle	
		Addr	Data	Addr	Data	Addr	Data	Addr	Data
Fast Mode Set	3	XXXH	AAH	XXXH	55H	XXXH	20H	—	—
Fast Program *1	2	XXXH	A0H	PA	PD	—	—	—	—
Fast Mode Reset *1	2	XXXH	90H	XXXH	F0H *3	—	—	—	—
Extended Sector Protection *2	4	XXXH	60H	SPA	60H	SPA	40H	SPA	SD

SPA: Sector address to be protected. Set sector address (SA) and (A₁₀, A₆, A₁, A₀) = (0, 0, 1, 0).

SD: Sector protection verify data. Output 01H at protected sector addresses and output 00H at unprotected sector addresses.

*1: This command is valid while Fast Mode.

*2: This command is valid while $\overline{\text{RESET}} = \text{V}_{\text{ID}}$.

*3: The data "00H" is also acceptable.

Read/Reset Command

The read or reset operation is initiated by writing the Read/Reset command sequence into the command register. Microprocessor read cycles retrieve array data from the memory. The device remains enabled for reads until the command register contents are altered.

The devices will automatically power-up in the read/reset state. In this case, a command sequence is not required to read data. Standard microprocessor read cycles will retrieve array data. This default value ensures that no spurious alteration of the memory content occurs during the power transition. Refer to the AC Read Characteristics and Waveforms for the specific timing parameters. (See Figures 5.1 and 5.2.)

Autoselect Command

Flash memories are intended for use in applications where the local CPU alters memory contents. As such, manufacture and device codes must be accessible while the device resides in the target system. PROM programmers typically access the signature codes by raising A₉ to a high voltage. However, multiplexing high voltage onto the address lines is not generally desired system design practice.

The device contains an Autoselect command operation to supplement traditional PROM programming methodology. The operation is initiated by writing the Autoselect command sequence into the command register. Following the command write, a read cycle from address XX00H retrieves the manufacture code of 04H. A read cycle from address X001H returns the device code (MBM29LV080A = 38H). (See Tables 3.1 and 3.2.)

All manufacturer and device codes will exhibit odd parity with the MSB (DQ₇) defined as the parity bit.

Sector state (protection or unprotection) will be informed address X0002H.

Scanning the sector addresses (A₁₉, A₁₈, A₁₇, A₁₆) while (A₁₀, A₆, A₁, A₀) = (0, 0, 1, 0) will produce a logical "1" at device output DQ₀ for a protected sector. The programming verification should be performed in margin mode on the protected sector. (See Table 2.)

To terminate the operation, it is necessary to write the Read/Reset command sequence into the register, and also to write the Autoselect command during the operation, execute it after writing Read/Reset command sequence.

Byte Programming

The device is programmed on a byte-by-byte basis. Programming is a four bus cycle operation. There are two “unlock” write cycles. These are followed by the program set-up command and data write cycles. Addresses are latched on the falling edge of \overline{CE} or \overline{WE} , whichever happens later and the data is latched on the rising edge of \overline{CE} or \overline{WE} , whichever happens first. The rising edge of \overline{CE} or \overline{WE} (whichever happens first) begins programming. Upon executing the Embedded Program Algorithm command sequence, the system is not required to provide further controls or timings. The device will automatically provide adequate internally generated program pulses and verify the programmed cell margin.

The automatic programming operation is completed when the data on DQ_7 is equivalent to data written to this bit at which time the device returns to the read mode and addresses are no longer latched. (See Table 8, Hardware Sequence Flags.) Therefore, the device requires that a valid address to the device be supplied by the system at this particular instance of time. Hence, \overline{Data} Polling must be performed at the memory location which is being programmed.

Any commands written to the chip during this period will be ignored. If hardware reset occurs during the programming operation, it is impossible to guarantee the data are being written.

Programming is allowed in any sequence and across sector boundaries. Beware that a data “0” cannot be programmed back to a “1”. Attempting to do so may either hang up the device (exceed timing limits), or result in an apparent success according to the data polling algorithm but a read from read/reset mode will show that the data is still “0”. Only erase operations can convert “0”s to “1”s.

Figure 17 illustrates the Embedded Program™ Algorithm using typical command strings and bus operations.

Chip Erase

Chip erase is a six bus cycle operation. There are two “unlock” write cycles. These are followed by writing the “set-up” command. Two more “unlock” write cycles are then followed by the Chip Erase command.

Chip erase does not require the user to program the device prior to erase. Upon executing the Embedded Erase Algorithm command sequence the device will automatically program and verify the entire memory for an all zero data pattern prior to electrical erase. The system is not required to provide any controls or timings during these operations.

The automatic erase begins on the rising edge of the last \overline{WE} pulse in the command sequence and terminates when the data on DQ_7 is “1” (See Write Operation Status section.) at which time the device returns to read the mode.

Figure 18 illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

Sector Erase

Sector erase is a six bus cycle operation. There are two “unlock” write cycles. These are followed by writing the “set-up” command. Two more “unlock” write cycles are then followed by the Sector Erase command. The sector address (any address location within the desired sector) is latched on the falling edge of \overline{WE} , while the command (Data = 30H) is latched on the rising edge of \overline{WE} . After time-out of 50 μ s from the rising edge of the last Sector Erase command, the sector erase operation will begin.

Multiple sectors may be erased concurrently by writing the six bus cycle operations on Table 6. This sequence is followed with writes of the Sector Erase command to addresses in other sectors desired to be concurrently erased. The time between writes must be less than 50 μ s, otherwise that command will not be accepted and erasure will start. It is recommended that processor interrupts be disabled during this time to guarantee this condition. The interrupts can be re-enabled after the last Sector Erase command is written. A time-out of 50 μ s from the rising edge of the last \overline{WE} will initiate the execution of the Sector Erase command(s). If another falling edge of the \overline{WE} occurs within the 50 μ s time-out window the timer is reset. (Monitor DQ_3 to determine if the sector erase timer window is still open, see section DQ_3 , Sector Erase Timer.) Any command other than Sector Erase or Erase Suspend during this time-out period will reset the devices to the read mode, ignoring the previous command string. Resetting the devices once execution has begun will corrupt the data in that sector. In that case, restart the erase on those sectors and allow them to complete. (Refer to the Write Operation Status section

for Sector Erase Timer operation.) Loading the sector erase buffer may be done in any sequence and with any number of sectors (0 to 15).

Sector erase does not require the user to program the devices prior to erase. The device automatically programs all memory locations in the sector(s) to be erased prior to electrical erase. When erasing a sector or sectors the remaining unselected sectors are not affected. The system is not required to provide any controls or timings during these operations.

The automatic sector erase begins after the 50 μ s time out from the rising edge of the \overline{WE} pulse for the last sector erase command pulse and terminates when the data on DQ₇ is "1" (See Write Operation Status section) at which time the device returns to the read mode. \overline{Data} polling must be performed at an address within any of the sectors being erased. Multiple Sector Erase Time; [Sector Program Time (Preprogramming) + Sector Erase Time] \times Number of Sector Erase.

Figure 18 illustrates the Embedded Erase™ Algorithm using typical command strings and bus operations.

Erase Suspend/Resume

The Erase Suspend command allows the user to interrupt a Sector Erase operation and then perform data reads from or program to a sector not being erased. This command is applicable ONLY during the Sector Erase operation which includes the time-out period for sector erase. The Erase Suspend command will be ignored if written during the Chip Erase operation or Embedded Program Algorithm. Writing the Erase Suspend command during the Sector Erase time-out results in immediate termination of the time-out period and suspension of the erase operation.

Writing the Erase Resume command resumes the erase operation. The addresses are "DON'T CARES" when writing the Erase Suspend or Erase Resume commands.

When the Erase Suspend command is written during the Sector Erase operation, the device will take a maximum of 20 μ s to suspend the erase operation. When the devices have entered the erase-suspended mode, the RY/ \overline{BY} output pin and the DQ₇ bit will be at logic "1", and DQ₆ will stop toggling. The user must use the address of the erasing sector for reading DQ₆ and DQ₇ to determine if the erase operation has been suspended. Further writes of the Erase Suspend command are ignored.

When the erase operation has been suspended, the device defaults to the erase-suspend-read mode. Reading data in this mode is the same as reading from the standard read mode except that the data must be read from sectors that have not been erase-suspended. Successively reading from the erase-suspended sector while the device is in the erase-suspend-read mode will cause DQ₂ to toggle. (See the section on DQ₂.)

After entering the erase-suspend-read mode, the user can program the device by writing the appropriate command sequence for Program. This Program mode is known as the erase-suspend-program mode. Again, programming in this mode is the same as programming in the regular Program mode except that the data must be programmed to sectors that are not erase-suspended. Successively reading from the erase-suspended sector while the devices are in the erase-suspend-program mode will cause DQ₂ to toggle. The end of the erase-suspended Program operation is detected by the RY/ \overline{BY} output pin, \overline{Data} polling of DQ₇, or the Toggle Bit (DQ₆) which is the same as the regular Program operation. Note that DQ₇ must be read from the Program address while DQ₆ can be read from any address.

To resume the operation of Sector Erase, the Resume command (30H) should be written. Any further writes of the Resume command at this point will be ignored. Another Erase Suspend command can be written after the chip has resumed erasing.

Extended Command

(1) Fast Mode

MBM29LV080A has Fast Mode function. This mode dispenses with the initial two unlock cycles required in the standard program command sequence by writing Fast mode command into the command register. In this mode, the required bus cycle for programming is two cycles instead of four bus cycles in normal command. (Do not write erase command in this mode.) The read operation is also executed after exiting this mode. To exit this mode, it is necessary to write Fast Mode Reset command into the command register. (Refer to the Figure 23 Extended algorithm.) The V_{CC} active current is required even $\overline{CE} = V_{IH}$ during Fast Mode.

(2) Fast Programming

During Fast Mode, the programming can be executed with two bus cycles operation. The Embedded Program Algorithm is executed by writing program Setup command (A0H) and data write cycles (PA/PD). (Refer to the Figure 23 Extended algorithm.)

(3) Extended Sector Protection

In addition to normal sector protection, the MBM29LV080A has Extended Sector Protection as extended function. This function enable to protect sector by forcing V_{ID} on \overline{RESET} pin and write a command sequence. Unlike conventional procedure, it is not necessary to force V_{ID} and control timing for control pins. The only \overline{RESET} pin requires V_{ID} for sector protection in this mode. The extended sector protect requires V_{ID} on \overline{RESET} pin. With this condition, the operation is initiated by writing the Setup command (60H) into the command register. Then, the sector addresses pins (A_{19} , A_{18} , A_{17} , and A_{16}) and (A_{10} , A_6 , A_1 , A_0) = (0, 0, 1, 0) should be set to the sector to be protected (recommend to set V_{IL} for the other addresses pins), and write extended sector protect command (60H). A sector is typically protected in 250 μ s. To verify programming of the protection circuitry, the sector addresses pins (A_{19} , A_{18} , A_{17} , and A_{16}) and (A_{10} , A_6 , A_1 , A_0) = (0, 0, 1, 0) should be set and write a command (40H). Following the command write, a logical "1" at device output DQ_0 will produce for protected sector in the read operation. If the output data is logical "0", please repeat to write extended sector protect command (60H) again. To terminate the operation, it is necessary to set \overline{RESET} pin to V_{IH} .

Write Operation Status

Table 7 Hardware Sequence Flags

Status		DQ ₇	DQ ₆	DQ ₅	DQ ₃	DQ ₂	
In Progress	Embedded Program Algorithm	$\overline{DQ_7}$	Toggle	0	0	1	
	Embedded/Erase Algorithm	0	Toggle	0	1	Toggle	
	Erase Suspend Mode	Erase Suspend Read (Erase Suspended Sector)	1	1	0	0	Toggle
		Erase Suspend Read (Non-Erase Suspended Sector)	Data	Data	Data	Data	Data
	Erase Suspend Program (Non-Erase Suspended Sector)	$\overline{DQ_7}$	Toggle (Note 1)	0	0	1 (Note 2)	
Exceeded Time Limits	Embedded Program Algorithm	$\overline{DQ_7}$	Toggle	1	0	1	
	Embedded/Erase Algorithm	0	Toggle	1	1	N/A	
	Erase Suspend Program (Non-Erase Suspended Sector)	$\overline{DQ_7}$	Toggle	1	0	N/A	

- Notes:
1. Performing successive read operations from any address will cause DQ₆ to toggle.
 2. Reading the byte address being programmed while in the erase-suspend program mode will indicate logic "1" at the DQ₂ bit. However, successive reads from the erase-suspended sector will cause DQ₂ to toggle.
 3. DQ₀ and DQ₁ are reserve pins for future use.
 4. DQ₄ is Fujitsu internal use only.

DQ₇

Data Polling

The MBM29LV080A device features $\overline{\text{Data}}$ Polling as a method to indicate to the host that the Embedded Algorithms are in progress or completed. During the Embedded Program Algorithm, an attempt to read the device will produce the complement of the data last written to DQ₇. Upon completion of the Embedded Program Algorithm, an attempt to read the device will produce the true data last written to DQ₇. During the Embedded Erase Algorithm, an attempt to read the device will produce a “0” at the DQ₇ output. Upon completion of the Embedded Erase Algorithm an attempt to read the device will produce a “1” at the DQ₇ output. The flowchart for $\overline{\text{Data}}$ Polling (DQ₇) is shown in Figure 19.

For chip erase and sector erase, the $\overline{\text{Data}}$ Polling is valid after the rising edge of the sixth $\overline{\text{WE}}$ pulse in the six write pulse sequence. $\overline{\text{Data}}$ Polling must be performed at sector address within any of the sectors being erased and not a protected sector. Otherwise, the status may not be valid. Once the Embedded Algorithm operation is close to being completed, the MBM29LV080A data pins (DQ₇) may change asynchronously while the output enable ($\overline{\text{OE}}$) is asserted low. This means that the device is driving status information on DQ₇ at one instant of time and then that byte's valid data at the next instant of time. Depending on when the system samples the DQ₇ output, it may read the status or valid data. Even if the device has completed the Embedded Algorithm operation and DQ₇ has a valid data, the data outputs on DQ₀ to DQ₆ may be still invalid. The valid data on DQ₀ to DQ₇ will be read on the successive read attempts.

The $\overline{\text{Data}}$ Polling feature is only active during the Embedded Programming Algorithm, Embedded Erase Algorithm, or sector erase time-out. (See Table 8.)

See Figure 9 for the $\overline{\text{Data}}$ Polling timing specifications and diagrams.

DQ₆

Toggle Bit I

The MBM29LV080A also features the “Toggle Bit I” as a method to indicate to the host system that the Embedded Algorithms are in progress or completed.

During an Embedded Program or Erase Algorithm cycle, successive attempts to read ($\overline{\text{OE}}$ toggling) data from the devices will result in DQ₆ toggling between one and zero. Once the Embedded Program or Erase Algorithm cycle is completed, DQ₆ will stop toggling and valid data will be read on the next successive attempts. During programming, the Toggle Bit I is valid after the rising edge of the fourth $\overline{\text{WE}}$ pulse in the four write pulse sequence. For chip erase and sector erase, the Toggle Bit I is valid after the rising edge of the sixth $\overline{\text{WE}}$ pulse in the six write pulse sequence. The Toggle Bit I is active during the sector time out.

In programming, if the sector being written to is protected, the toggle bit will toggle for about 2 μs and then stop toggling without the data having changed. In erase, the device will erase all the selected sectors except for the ones that are protected. If all selected sectors are protected, the chip will toggle the toggle bit for about 50 μs and then drop back into read mode, having changed none of the data.

Either $\overline{\text{CE}}$ or $\overline{\text{OE}}$ toggling will cause the DQ₆ to toggle. In addition, an Erase Suspend/Resume command will cause the DQ₆ to toggle.

See Figure 10 and Figure 20 for the Toggle Bit I timing specifications and diagrams.

DQ₅**Exceeded Timing Limits**

DQ₅ will indicate if the program or erase time has exceeded the specified limits (internal pulse count). Under these conditions DQ₅ will produce a “1”. This is a failure condition which indicates that the program or erase cycle was not successfully completed. $\overline{\text{Data}}$ Polling DQ₇, DQ₆ is the only operating function of the device under this condition. The $\overline{\text{CE}}$ circuit will partially power down the device under these conditions (to approximately 2 mA). The $\overline{\text{OE}}$ and $\overline{\text{WE}}$ pins will control the output disable functions as described in Table 2.

The DQ₅ failure condition may also appear if a user tries to program a non blank location without erasing. In this case the device locks out and never completes the Embedded Algorithm operation. Hence, the system never reads a valid data on DQ₇ bit and DQ₆ never stops toggling. Once the device has exceeded timing limits, the DQ₅ bit will indicate a “1” Please note that this is not a device failure condition since the device was incorrectly used. If this occurs, reset the device with command sequence.

DQ₃**Sector Erase Timer**

After the completion of the initial Sector Erase command sequence the sector erase time-out will begin. DQ₃ will remain low until the time-out is complete. $\overline{\text{Data}}$ Polling and Toggle Bit are valid after the initial Sector Erase command sequence.

If $\overline{\text{Data}}$ Polling or the Toggle Bit I indicates the device has been written with a valid erase command, DQ₃ may be used to determine if the sector erase timer window is still open. If DQ₃ is high (“1”) the internally controlled erase cycle has begun; attempts to write subsequent commands to the device will be ignored until the erase operation is completed as indicated by $\overline{\text{Data}}$ Polling or Toggle Bit I. If DQ₃ is low (“0”), the device will accept additional Sector Erase commands. To insure the command has been accepted, the system software should check the status of DQ₃ prior to and following each subsequent sector erase command. If DQ₃ were high on the second status check, the command may not have been accepted.

See Table 8: Hardware Sequence Flags.

DQ₂**Toggle Bit II**

This Toggle Bit II, along with DQ₆, can be used to determine whether the devices are in the Embedded Erase Algorithm or in Erase Suspend.

Successive reads from the erasing sector will cause DQ₂ to toggle during the Embedded Erase Algorithm. If the devices are in the erase-suspended-read mode, successive reads from the erase-suspended sector will cause DQ₂ to toggle. When the devices are in the erase-suspended-program mode, successive reads from the byte address of the non-erase suspended sector will indicate a logic “1” at the DQ₂ bit.

DQ₆ is different from DQ₂ in that DQ₆ toggles only when the standard program or Erase, or Erase Suspend Program operation is in progress.

For example, DQ₂ and DQ₆ can be used together to determine the erase-suspend-read mode. (DQ₂ toggles while DQ₆ does not.) See also above Table 9 and Figure 16.

Furthermore, DQ₂ can also be used to determine which sector is being erased. When the devices are in the erase mode, DQ₂ toggles if this bit is read from the erasing sector.

Table 8 Toggle Bit Status

Mode	DQ ₇	DQ ₆	DQ ₂
Program	$\overline{DQ_7}$	Toggle	1
Erase	0	Toggle	Toggle
Erase-Suspend Read (Erase-Suspended Sector) (Note 1)	1	1	Toggle
Erase-Suspend Program	$\overline{DQ_7}$	Toggle (Note 1)	1 (Note 2)

Notes: 1. Performing successive read operations from any address will cause DQ₆ to toggle.

2. Reading the address being programmed while in the erase-suspend program mode will indicate logic “1” at the DQ₂ bit. However, successive reads from the erase-suspended sector will cause DQ₂ to toggle.

$\overline{RY/BY}$

Ready/Busy Pin

The MBM29LV080A provides a $\overline{RY/BY}$ open-drain output pin as a way to indicate to the host system that the Embedded Algorithms are either in progress or has been completed. If the output is low, the device is busy with either a program or erase operation. If the output is high, the device is ready to accept any read/write or erase operation. When the $\overline{RY/BY}$ pin is low, the device will not accept any additional program or erase commands with the exception of the Erase Suspend command. If the MBM29LV080A is placed in an Erase Suspend mode, the $\overline{RY/BY}$ output will be high, by means of connecting with a pull up resistor to V_{CC}.

During programming, the $\overline{RY/BY}$ pin is driven low after the rising edge of the fourth \overline{WE} pulse. During an erase operation, the $\overline{RY/BY}$ pin is driven low after the rising edge of the sixth \overline{WE} pulse. The $\overline{RY/BY}$ pin will indicate a busy condition during the \overline{RESET} pulse. See Figure 11 and 12 for a detailed timing diagram. The $\overline{RY/BY}$ pin is pulled high in standby mode.

Since this is an open-drain output, $\overline{RY/BY}$ pins can be tied together in parallel with a pull-up resistor to V_{CC}.

\overline{RESET}

Hardware Reset Pin

The MBM29LV080A device may be reset by driving the \overline{RESET} pin to V_{IL}. The \overline{RESET} pin has a pulse requirement and has to be kept low (V_{IL}) for at least 500 ns in order to properly reset the internal state machine. Any operation in the process of being executed will be terminated and the internal state machine will be reset to the read mode t_{READY} after the \overline{RESET} pin is driven low. Furthermore, once the \overline{RESET} pin goes high, the device requires an additional t_{RH} before it will allow read access. When the \overline{RESET} pin is low, the device will be in the standby mode for the duration of the pulse and all the data output pins will be tri-stated. If a hardware reset occurs during a program or erase operation, the data at that particular location will be corrupted. Please note that the $\overline{RY/BY}$ output signal should be ignored during the \overline{RESET} pulse. See Figure 12 for the timing diagram. Refer to Temporary Sector Unprotection for additional functionality.

If hardware reset occurs during Embedded Erase Algorithm, there is a possibility that the erasing sector(s) cannot be used.

Data Protection

The MBM29LV080A is designed to offer protection against accidental erasure or programming caused by spurious system level signals that may exist during power transitions. During power up the device automatically resets the internal state machine in the Read mode. Also, with its control register architecture, alteration of the memory contents only occurs after successful completion of specific multi-bus cycle command sequences.

The devices also incorporates several features to prevent inadvertent write cycles resulting from V_{CC} power-up and power-down transitions or system noise.

Low V_{CC} Write Inhibit

To avoid initiation of a write cycle during V_{CC} power-up and power-down, a write cycle is locked out for V_{CC} less than 2.3 V (typically 2.4 V). If $V_{CC} < V_{LKO}$, the command register is disabled and all internal program/erase circuits are disabled. Under this condition the device will reset to the Read mode. Subsequent writes will be ignored until the V_{CC} level is greater than V_{LKO} . It is the users responsibility to ensure that the control pins are logically correct to prevent unintentional writes when V_{CC} is above 2.3 V.

If Embedded Erase Algorithm is interrupted, there is possibility that the erasing sector(s) cannot be used.

Write Pulse “Glitch” Protection

Noise pulses of less than 5 ns (typical) on \overline{OE} , \overline{CE} , or \overline{WE} will not initiate a write cycle.

Logical Inhibit

Writing is inhibited by holding any one of $\overline{OE} = V_{IL}$, $\overline{CE} = V_{IH}$, or $\overline{WE} = V_{IH}$. To initiate a write cycle \overline{CE} and \overline{WE} must be a logical zero while \overline{OE} is a logical one.

Power-up Write Inhibit

Power-up of the device with $\overline{WE} = \overline{CE} = V_{IL}$ and $\overline{OE} = V_{IH}$ will not accept commands on the rising edge of \overline{WE} . The internal state machine is automatically reset to the read mode on power-up.

■ ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Conditions	Rating		Unit
			Min.	Max.	
Storage Temperature	T _{stg}	—	-55	+125	°C
Ambient Temperature with Power Applied	T _A	—	-40	+85	°C
Voltage with respect to Ground All pins except A ₉ , $\overline{\text{OE}}$, $\overline{\text{RESET}}$ (Note 1)	V _{IN} , V _{OUT}	—	-0.5	V _{CC} +0.5	V
Power Supply Voltage (Note 1)	V _{CC}	—	-0.5	+5.5	V
A ₉ , $\overline{\text{OE}}$, and $\overline{\text{RESET}}$ (Note 2)	V _{IN}	—	-0.5	+13.0	V

- Notes: 1. Minimum DC voltage on input or I/O pins is -0.5 V. During voltage transitions, input or I/O pins may undershoot V_{SS} to -2.0 V for periods of up to 20 ns. Maximum DC voltage on input or I/O pins is V_{CC} + 0.5 V. During voltage transitions, input or I/O pins may overshoot to V_{CC} + 2.0 V for periods of up to 20 ns.
2. Minimum DC input voltage on A₉, $\overline{\text{OE}}$ and $\overline{\text{RESET}}$ pins is -0.5 V. During voltage transitions, A₉, $\overline{\text{OE}}$ and $\overline{\text{RESET}}$ pins may undershoot V_{SS} to -2.0 V for periods of up to 20 ns. Voltage difference between input and supply voltage (V_{IN} - V_{CC}) does not exceed 9.0 V. Maximum DC input voltage on A₉, $\overline{\text{OE}}$ and $\overline{\text{RESET}}$ pins is +13.0 V which may overshoot to 14.0 V for periods of up to 20 ns.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING RANGES

Parameter	Symbol	Conditions	Value		Unit
			Min.	Max.	
Ambient Temperature	T _A	—	-40	+85	°C
Power Supply Voltage	V _{CC}	MBM29DL16XTE/BE-70	+3.0	+3.6	V
		MBM29DL16XTE/BE-90/12	+2.7	+3.6	V

Operating ranges define those limits between which the functionality of the device is guaranteed.

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representatives beforehand.

■ MAXIMUM OVERSHOOT / UNDERSHOOT

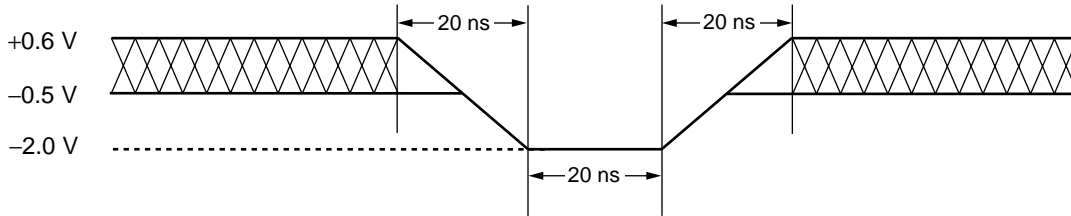


Figure 1 Maximum Undershoot Waveform

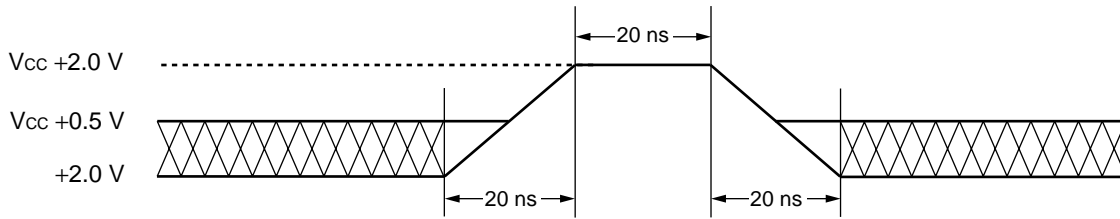
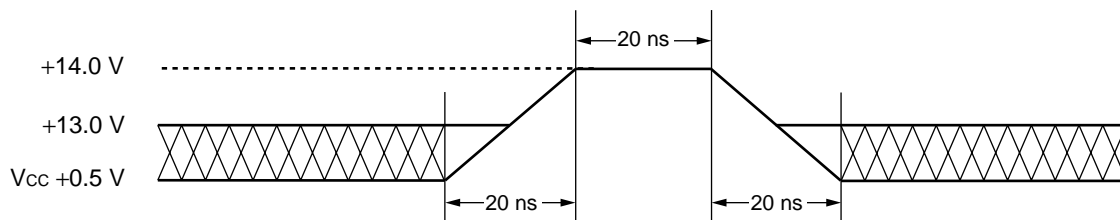


Figure 2 Maximum Overshoot Waveform 1



Note : This waveform is applied for A_9 , \overline{OE} and \overline{RESET} .

Figure 3 Maximum Overshoot Waveform 2

■ DC CHARACTERISTICS

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
I _{LI}	Input Leakage Current	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} Max.	-1.0	+1.0	μA
I _{LO}	Output Leakage Current	V _{OUT} = V _{SS} to V _{CC} , V _{CC} = V _{CC} Max.	-1.0	+1.0	μA
I _{LIT}	A ₉ , $\overline{\text{OE}}$, $\overline{\text{RESET}}$ Inputs Leakage Current	V _{CC} = V _{CC} Max., A ₉ , $\overline{\text{OE}}$, $\overline{\text{RESET}}$ = 12.5 V	—	35	μA
I _{CC1}	V _{CC} Active Current (Note 1)	$\overline{\text{CE}}$ = V _{IL} , $\overline{\text{OE}}$ = V _{IH} , f = 10 MHz	—	22	mA
		$\overline{\text{CE}}$ = V _{IL} , $\overline{\text{OE}}$ = V _{IH} , f = 5 MHz	—	12	mA
I _{CC2}	V _{CC} Active Current (Note 2)	$\overline{\text{CE}}$ = V _{IL} , $\overline{\text{OE}}$ = V _{IH}	—	35	mA
I _{CC3}	V _{CC} Current (Standby)	V _{CC} = V _{CC} Max., $\overline{\text{CE}}$ = V _{CC} ± 0.3 V, $\overline{\text{RESET}}$ = V _{CC} ± 0.3 V	—	5	μA
I _{CC4}	V _{CC} Current during Reset (Standby, $\overline{\text{RESET}}$)	V _{CC} = V _{CC} Max., $\overline{\text{RESET}}$ = V _{SS} ± 0.3 V	—	5	μA
I _{CC5}	V _{CC} Current (Automatic Sleep Mode) (Note 3)	V _{CC} = V _{CC} Max., $\overline{\text{RESET}}$ = V _{CC} ± 0.3 V, $\overline{\text{CE}}$ = V _{SS} ± 0.3 V, V _{IN} = V _{CC} ± 0.3 V or V _{SS} ± 0.3 V	—	5	μA
V _{IL}	Input Low Level	—	-0.5	0.6	V
V _{IH}	Input High Level	—	2.0	V _{CC} + 0.3	V
V _{ID}	Voltage for Autoselect, Sector Protection and Temporary Sector Unprotection (A ₉ , $\overline{\text{OE}}$, $\overline{\text{RESET}}$) (Note 4, 5)	—	11.5	12.5	V
V _{OL}	Output Low Voltage Level	I _{OL} = 4.0 mA, V _{CC} = V _{CC} Min.	—	0.45	V
V _{OH1}	Output High Voltage Level	I _{OH} = -2.0 mA, V _{CC} = V _{CC} Min.	2.4	—	V
V _{OH2}		I _{OH} = -100 μA	V _{CC} - 0.4	—	V
V _{LKO}	Low V _{CC} Lock-Out Voltage	—	2.3	2.5	V

- Notes: 1. The I_{CC} current listed includes both the DC operating current and the frequency dependent component.
 2. I_{CC} active while Embedded Erase or Embedded Program is in progress.
 3. Automatic sleep mode enables the low power mode when address remain stable for 150 ns.
 4. This voltage is for Sector Protection operation.
 5. (V_{ID} - V_{CC}) do not exceed 9 V.

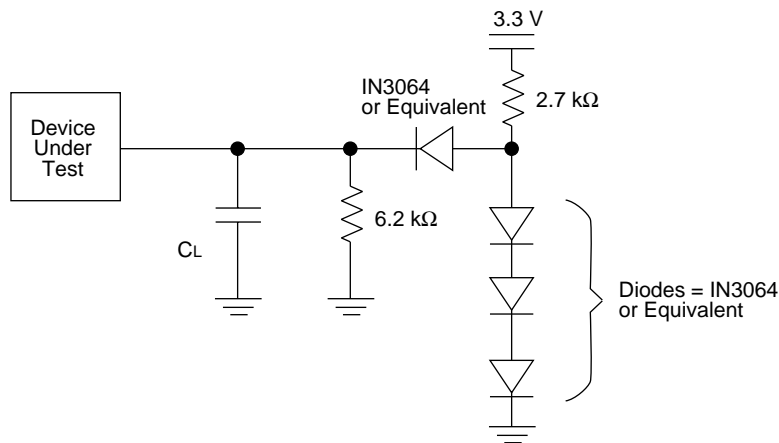
AC CHARACTERISTICS

Read Only Operations Characteristics

Parameter Symbols		Description	Test Setup		-70 (Note)	-90 (Note)	-12 (Note)	Unit
JEDEC	Standard							
t _{AVAV}	t _{RC}	Read Cycle Time	—	Min.	70	90	120	ns
t _{AVQV}	t _{ACC}	Address to Output Delay	$\overline{CE} = V_{IL}$ $\overline{OE} = V_{IL}$	Max.	70	90	120	ns
t _{ELQV}	t _{CE}	Chip Enable to Output Delay	$\overline{OE} = V_{IL}$	Max.	70	90	120	ns
t _{GLQV}	t _{OE}	Output Enable to Output Delay	—	Max.	30	35	50	ns
t _{EHQZ}	t _{DF}	Chip Enable to Output HIGH-Z	—	Max.	25	30	30	ns
t _{GHQZ}	t _{DF}	Output Enable to Output HIGH-Z	—	Max.	25	30	30	ns
t _{AXQX}	t _{OH}	Output Hold Time From Address, \overline{CE} or \overline{OE} , Whichever Occurs First	—	Min.	0	0	0	ns
—	t _{READY}	\overline{RESET} Pin Low to Read Mode	—	Max.	20	20	20	μs

Note: Test Conditions: Output Load: 1 TTL gate and 30 pF (MBM29LV080A-70)
 1 TTL gate and 100 pF (MBM29LV080A-90/-12)

Input rise and fall times: 5 ns
 Input pulse levels: 0.0 V to 3.0 V
 Timing measurement reference level
 Input: 1.5 V
 Output: 1.5 V



Notes: C_L = 30 pF including jig capacitance (MBM29LV080A-70)
 C_L = 100 pF including jig capacitance (MBM29LV080A-90/-12)

Figure 4 Test Conditions

MBM29LV080A-70/-90/-12

• Write (Erase/Program) Operations

Parameter Symbols		Description		MBM29LV080A			Unit
JEDEC	Standard			-70	-90	-12	
tAVAV	tWC	Write Cycle Time	Min.	70	90	120	ns
tAVWL	tAS	Address Setup Time	Min.	0	0	0	ns
tWLAX	tAH	Address Hold Time	Min.	45	45	50	ns
tDVWH	tDS	Data Setup Time	Min.	35	45	50	ns
tWHDX	tDH	Data Hold Time	Min.	0	0	0	ns
—	toES	Output Enable Setup Time	Min.	0	0	0	ns
—	toEH	Output Enable Hold Time	Read	Min.	0	0	ns
			Toggle and Data Polling	Min.	10	10	10
tGHWL	tGHWL	Read Recover Time Before Write (OE High to WE Low)	Min.	0	0	0	ns
tGHEL	tGHEL	Read Recover Time Before Write (OE High to CE Low)	Min.	0	0	0	ns
tELWL	tCS	CE Setup Time	Min.	0	0	0	ns
tWLEL	tWS	WE Setup Time	Min.	0	0	0	ns
tWHEH	tCH	CE Hold Time	Min.	0	0	0	ns
tEHWH	tWH	WE Hold Time	Min.	0	0	0	ns
tWLWH	tWP	Write Pulse Width	Min.	35	45	50	ns
tELEH	tCP	CE Pulse Width	Min.	35	45	50	ns
tWHWL	tWPH	Write Pulse Width High	Min.	25	25	30	ns
tEHEL	tCPH	CE Pulse Width High	Min.	25	25	30	ns
tWHWH1	tWHWH1	Programming Operation	Typ.	8	8	8	μs
tWHWH2	tWHWH2	Sector Erase Operation (Note 1)	Typ.	1	1	1	s
—	tEOE	Delay Time from Embedded Output Enable	Max.	30	35	50	ns
—	tVCS	VCC Setup Time	Min.	50	50	50	μs
—	tVLHT	Voltage Transition Time (Note 2)	Min.	4	4	4	μs
—	tWPP	Write Pulse Width (Note 2)	Min.	100	100	100	μs
—	toESP	OE Setup Time to WE Active (Note 2)	Min.	4	4	4	μs
—	tCSP	CE Setup Time to WE Active (Note 2)	Min.	4	4	4	μs
—	tRB	Recover Time From RY/BY	Min.	0	0	0	ns
—	tRH	RESET Hold Time Before Read	Min.	200	200	200	ns

(Continued)

(Continued)

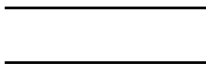
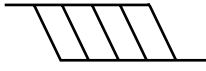

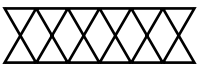
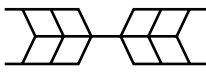
Parameter Symbols		Description		MBM29LV080A			Unit
JEDEC	Standard			-70	-90	-12	
—	t _{BUSY}	Program/Erase Valid to RY/ $\overline{\text{BY}}$ Delay	Max.	90	90	90	ns
—	t _{VIDR}	Rise Time to V _{ID} (Note 2)	Min.	500	500	500	ns
—	t _{RP}	$\overline{\text{RESET}}$ Pulse Width	Min.	500	500	500	ns

Notes: 1. This does not include the preprogramming time.

2. This timing is for Sector Protection operation.

SWITCHING WAVEFORMS

Key to Switching Waveforms

WAVEFORM	INPUTS	OUTPUTS
	Must Be Steady	Will Be Steady
	May Change from H to L	Will Be Change from H to L
	May Change from L to H	Will Be Change from L to H
	"H" or "L": Any Change Permitted	Changing, State Unknown
	Does Not Apply	Center Line is High-Impedance "Off" State

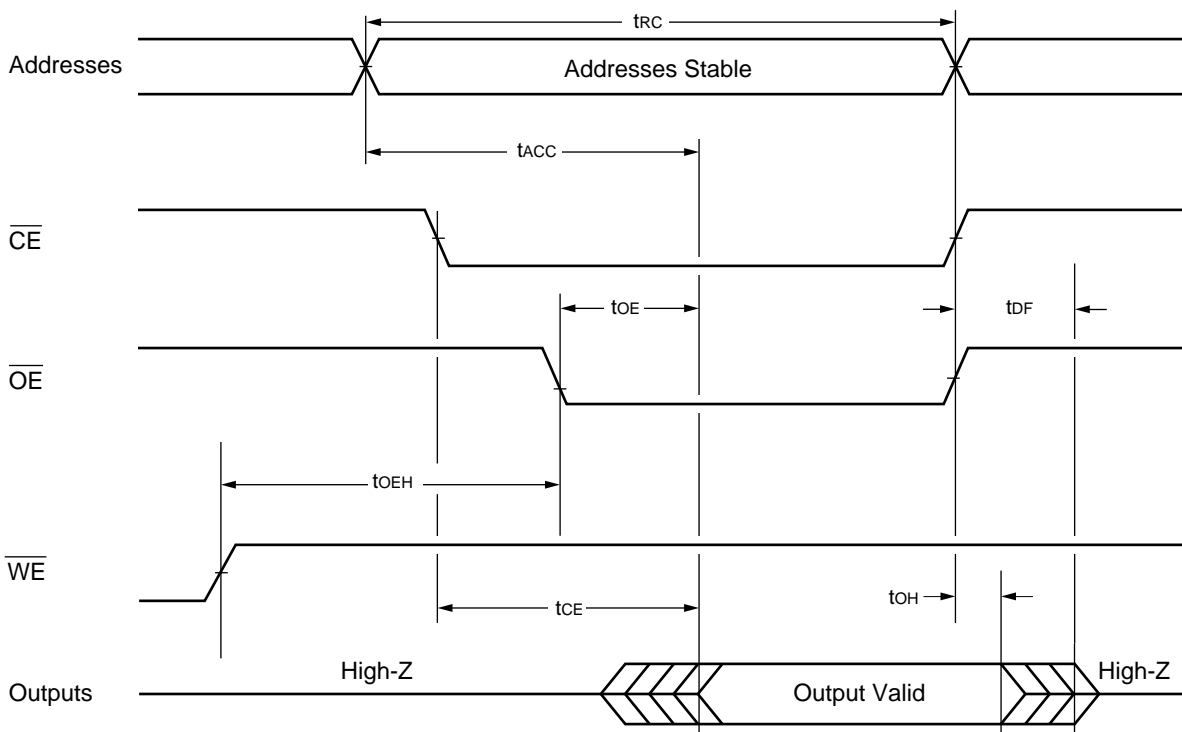


Figure 5.1 AC Waveforms for Read Operations

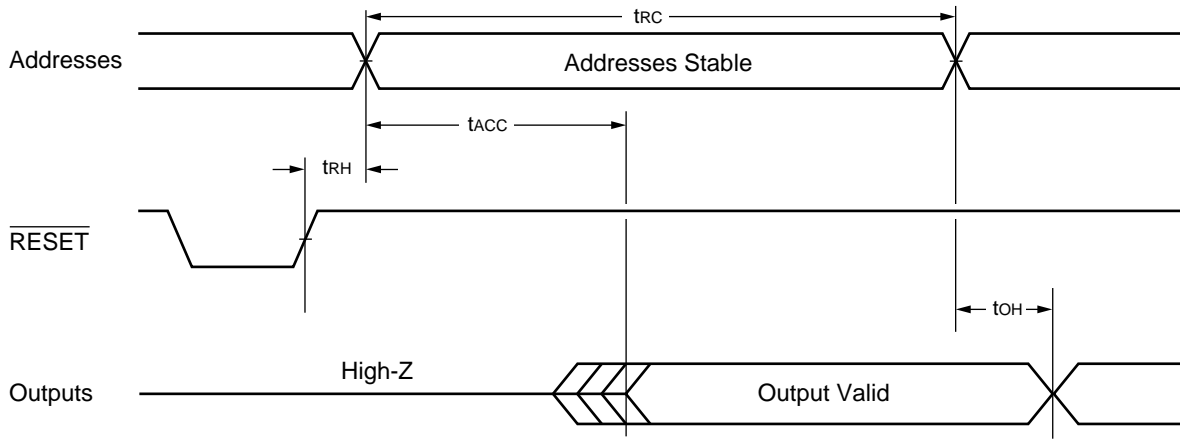
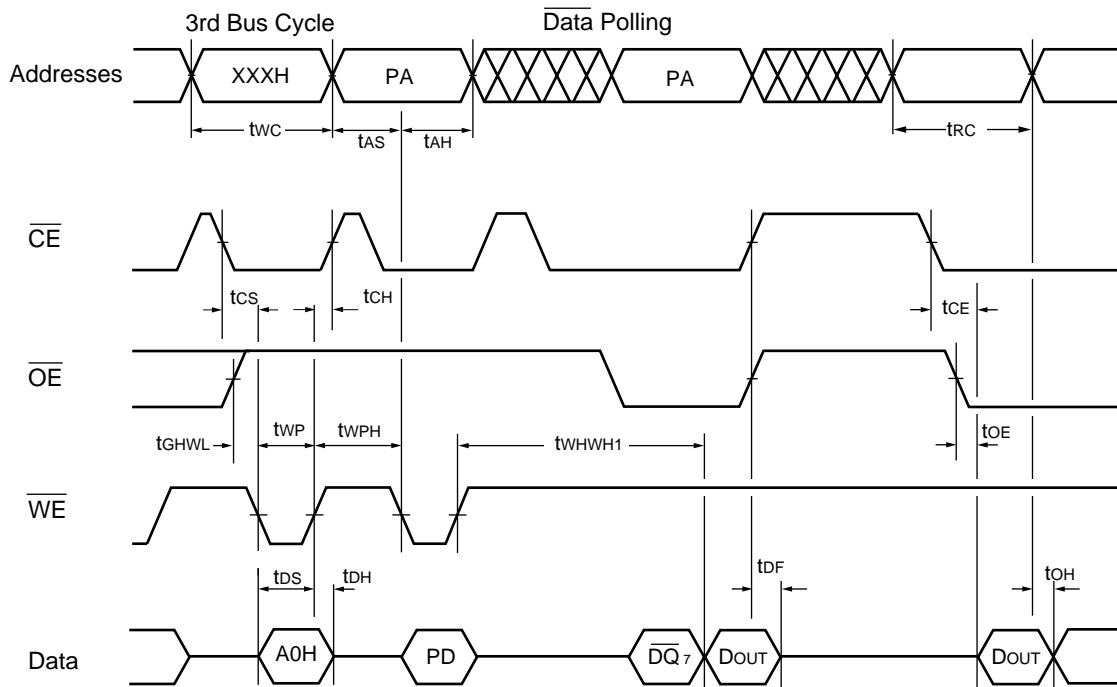
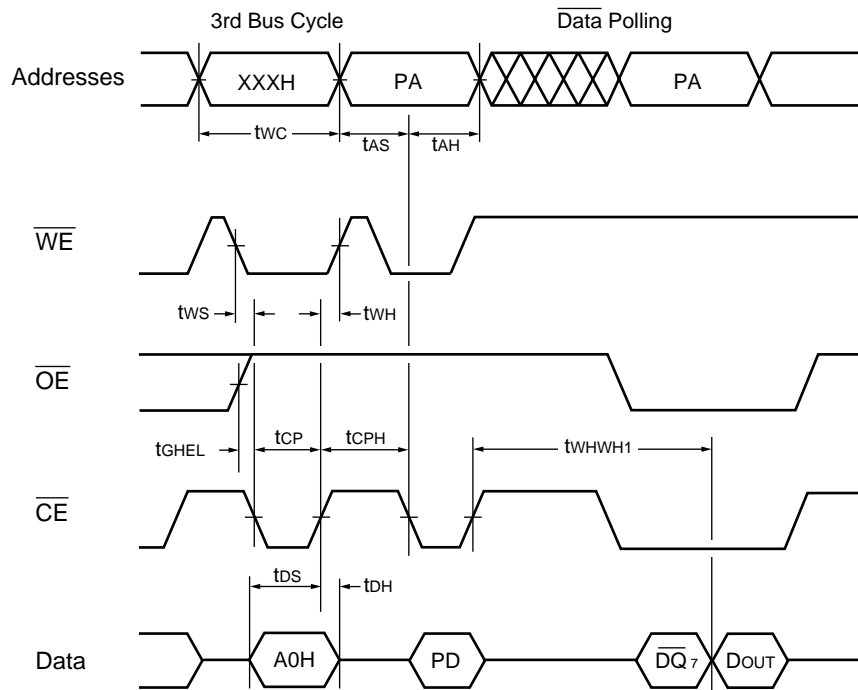


Figure 5.2 AC Waveforms for Hardware Reset/Read Operations



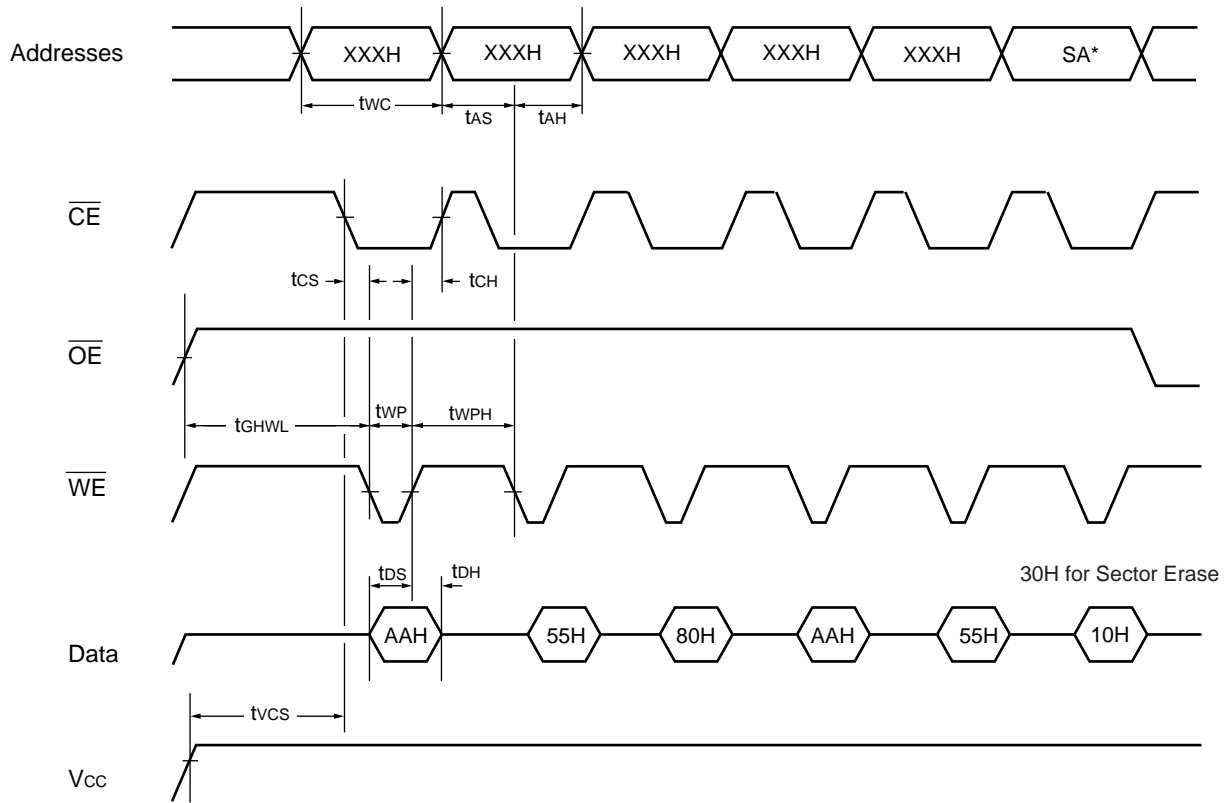
- Notes:
- PA is address of the memory location to be programmed.
 - PD is data to be programmed at byte address.
 - \overline{DQ}_7 is the output of the complement of the data written to the device.
 - D_{OUT} is the output of the data written to the device.
 - Figure indicates last two bus cycles out of four bus cycle sequence.

Figure 6 AC Waveforms for Alternate \overline{WE} Controlled Program Operations



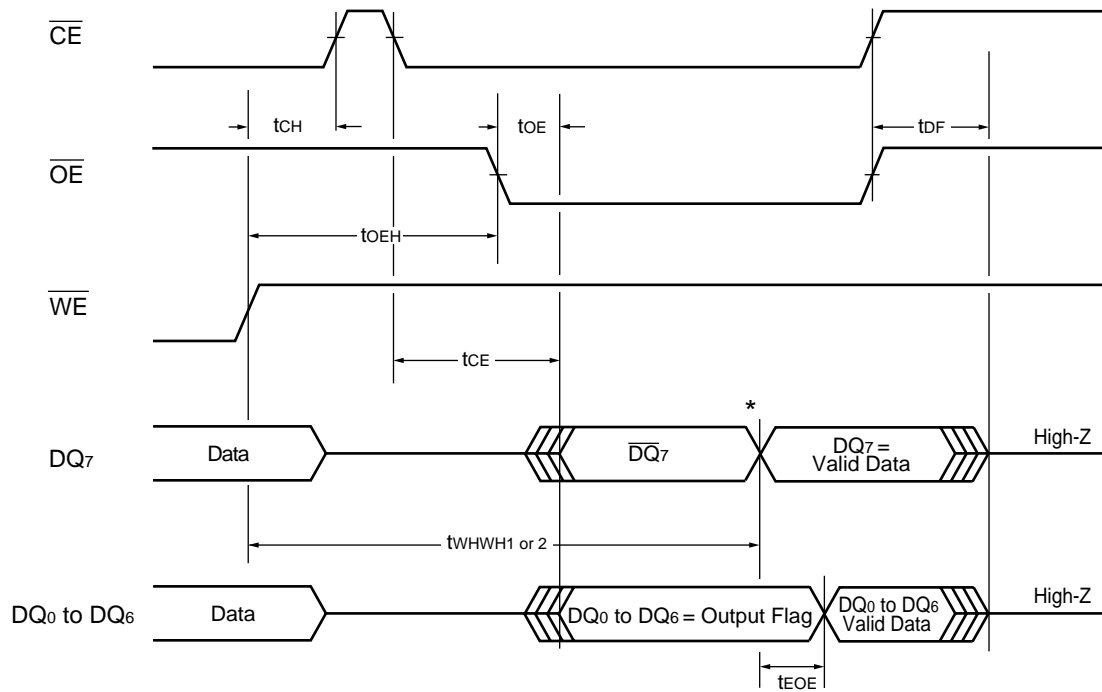
- Notes:
- PA is address of the memory location to be programmed.
 - PD is data to be programmed at byte address.
 - \overline{DQ}_7 is the output of the complement of the data written to the device.
 - D_{OUT} is the output of the data written to the device.
 - Figure indicates last two bus cycles out of four bus cycle sequence.

Figure 7 AC Waveforms for Alternate \overline{CE} Controlled Program Operations



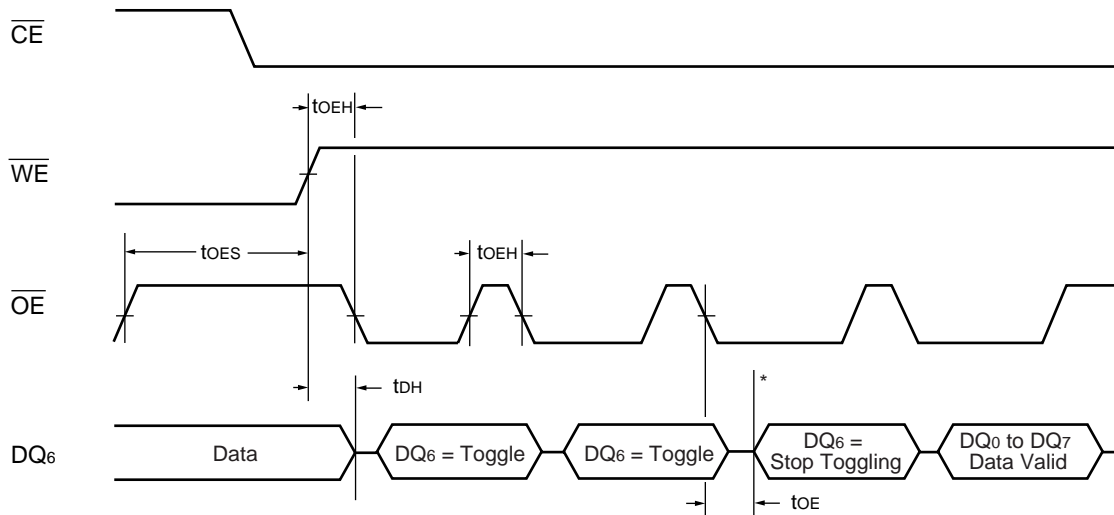
*: SA is the sector address for Sector Erase. Addresses = $XXXH$ for Chip Erase.

Figure 8 AC Waveforms for Chip/Sector Erase Operations



*: DQ₇ = Valid Data (The device has completed the Embedded operation.)

Figure 9 AC Waveforms for Data Polling during Embedded Algorithm Operations



*: DQ₆ stops toggling. (The device has completed the Embedded operation.)

Figure 10 AC Waveforms for Toggle Bit I during Embedded Algorithm Operations

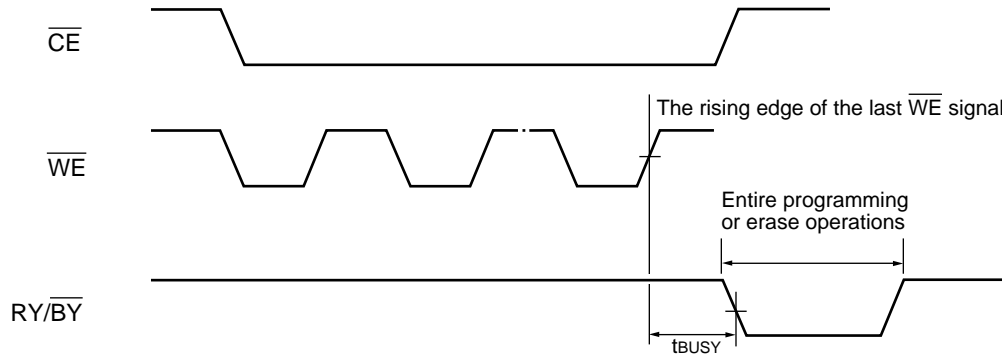


Figure 11 $\overline{RY/BY}$ Timing Diagram during Program/Erase Operations

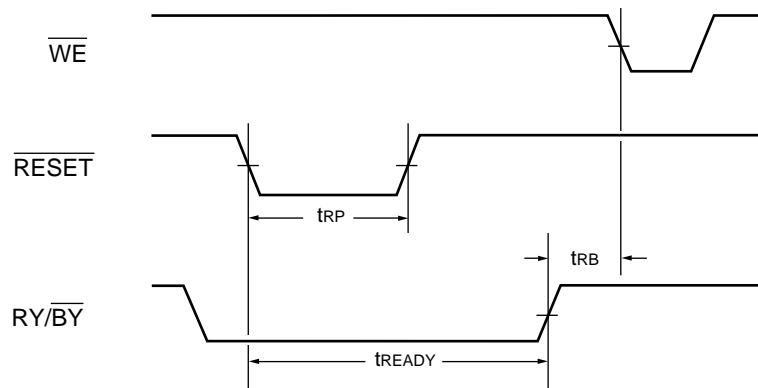
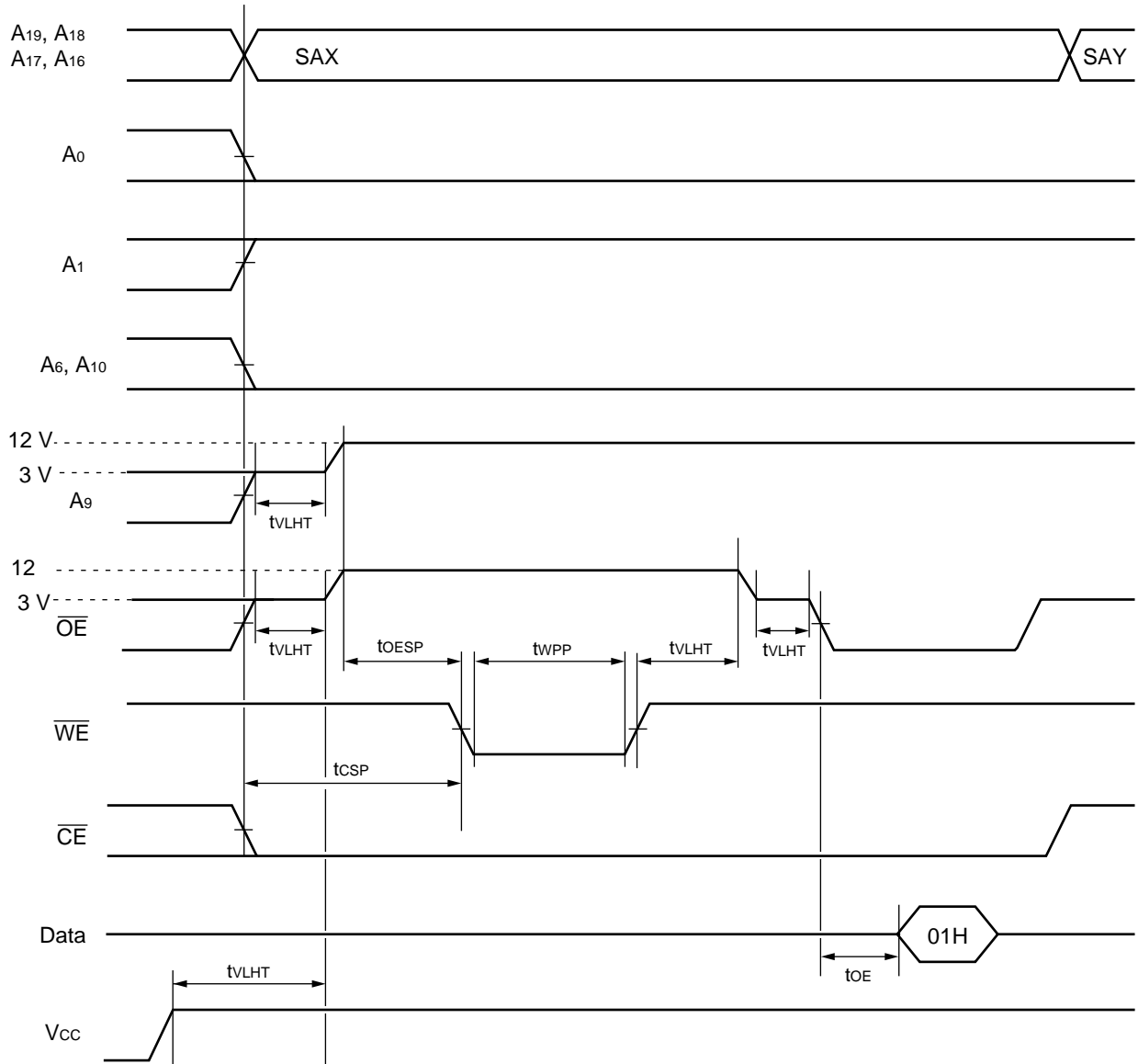
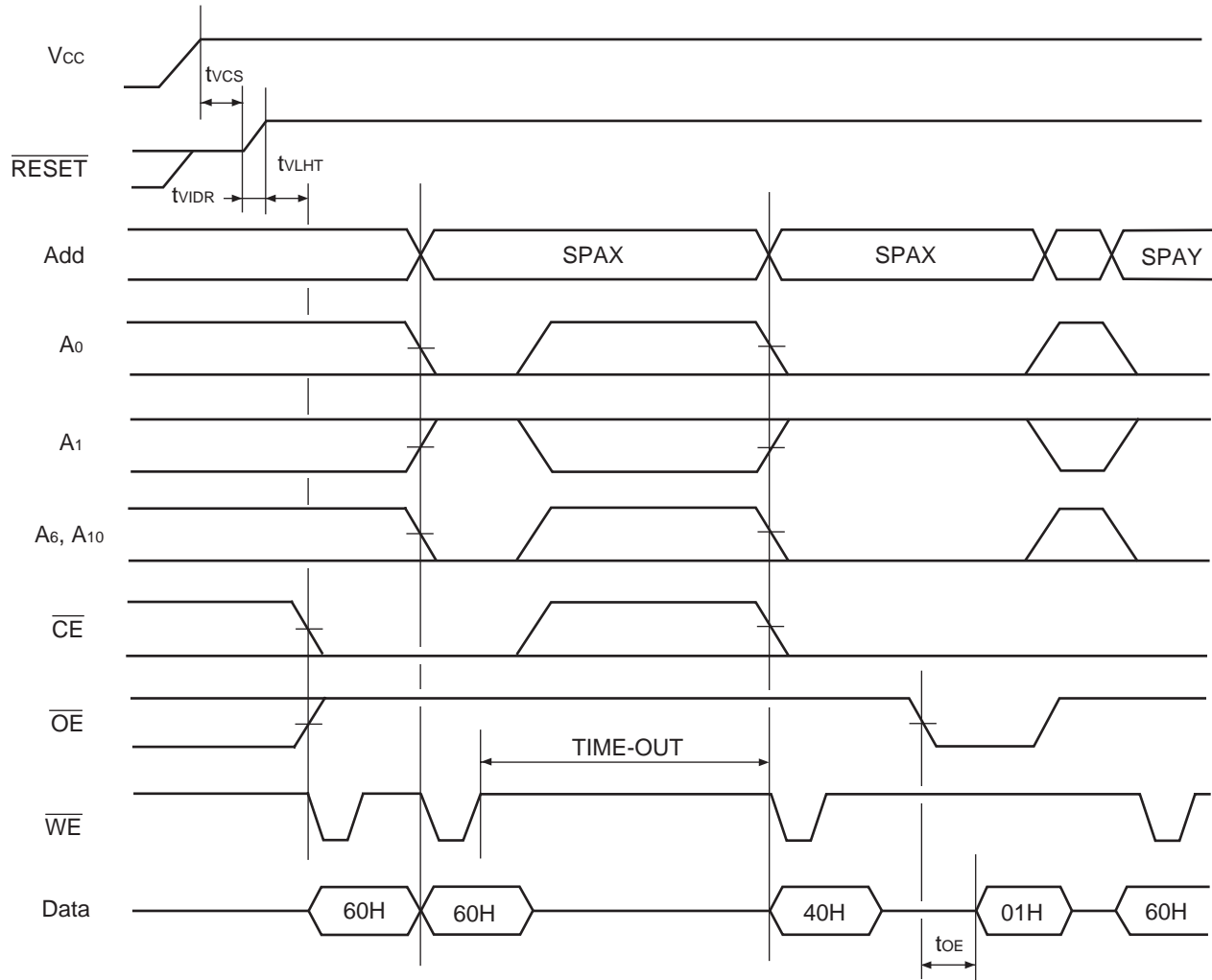


Figure 12 \overline{RESET} , $\overline{RY/BY}$ Timing Diagram



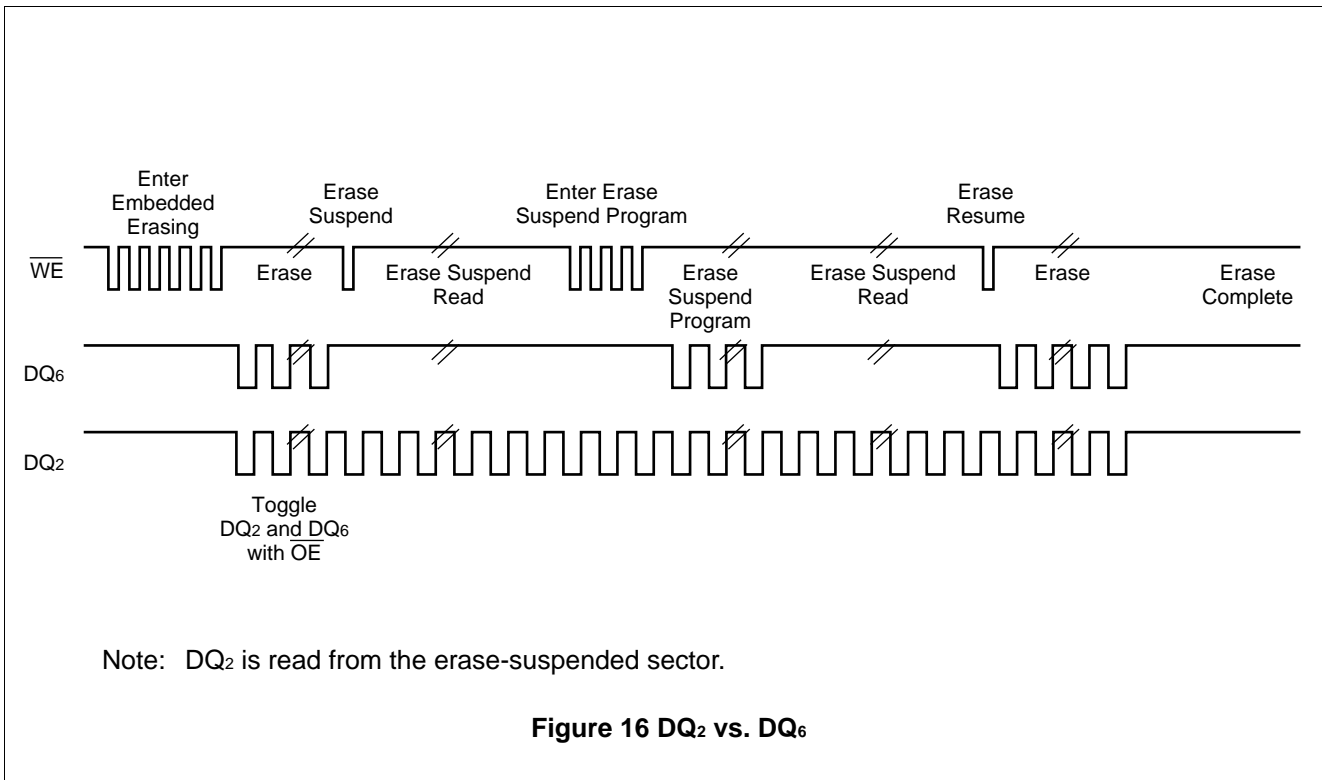
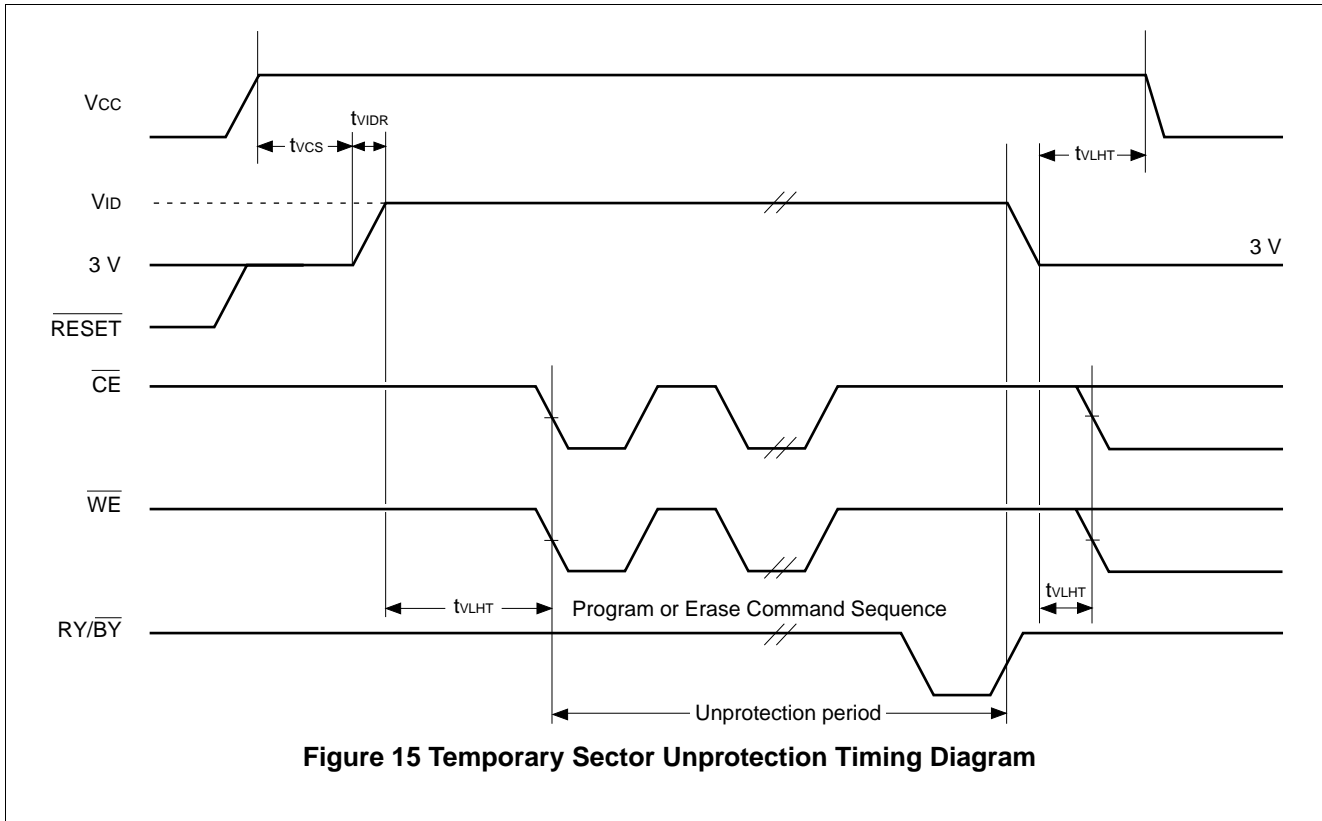
SAX: Sector Address for initial sector
 SAY : Sector Address for next sector

Figure 13 AC Waveforms for Sector Protection Timing Diagram



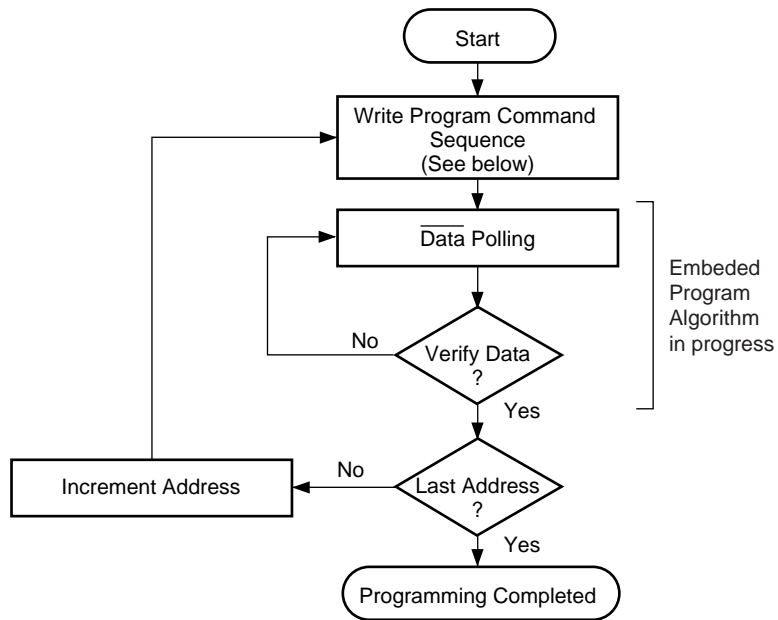
SPAX: Sector Address to be protected
 SPAY : Next Sector Address to be protected
 TIME-OUT : Time-Out window = 250 μ s (min.)

Figure 14 Extended Sector Protection Timing Diagram



■ FLOW CHART

EMBEDDED ALGORITHM



Program Command Sequence (Address/Command):

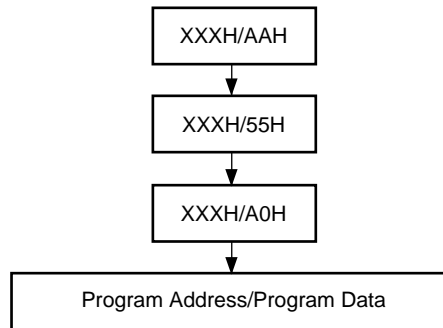


Figure 17 Embedded Program™ Algorithm

EMBEDDED ALGORITHM

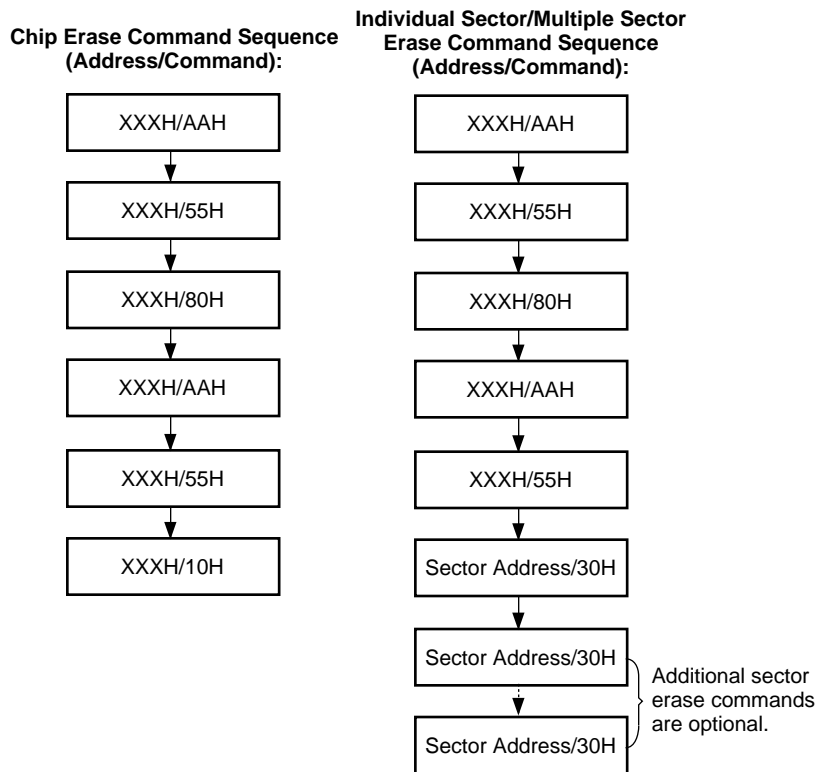
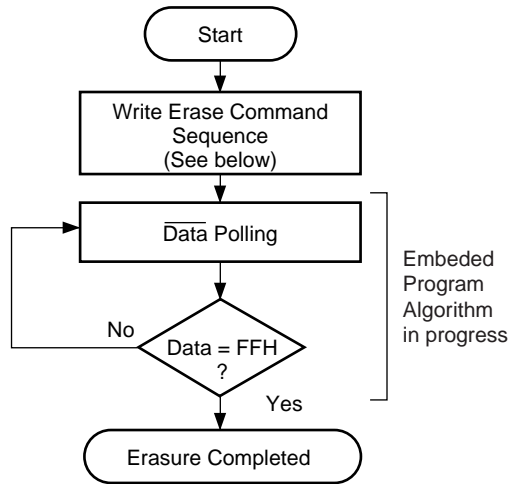
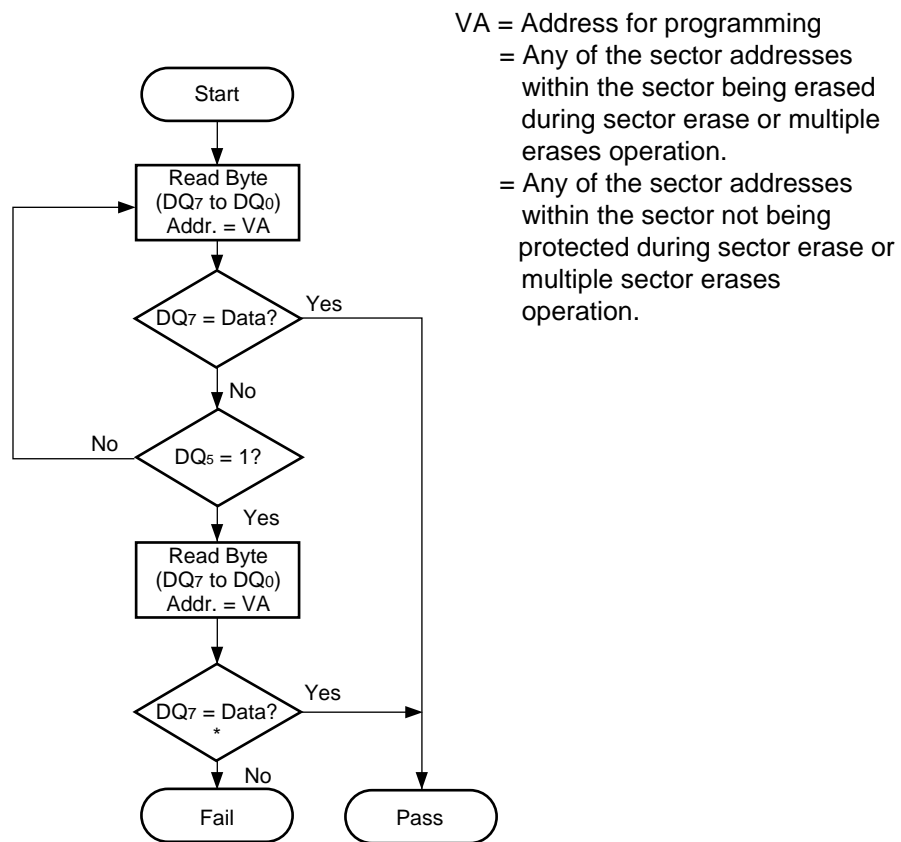
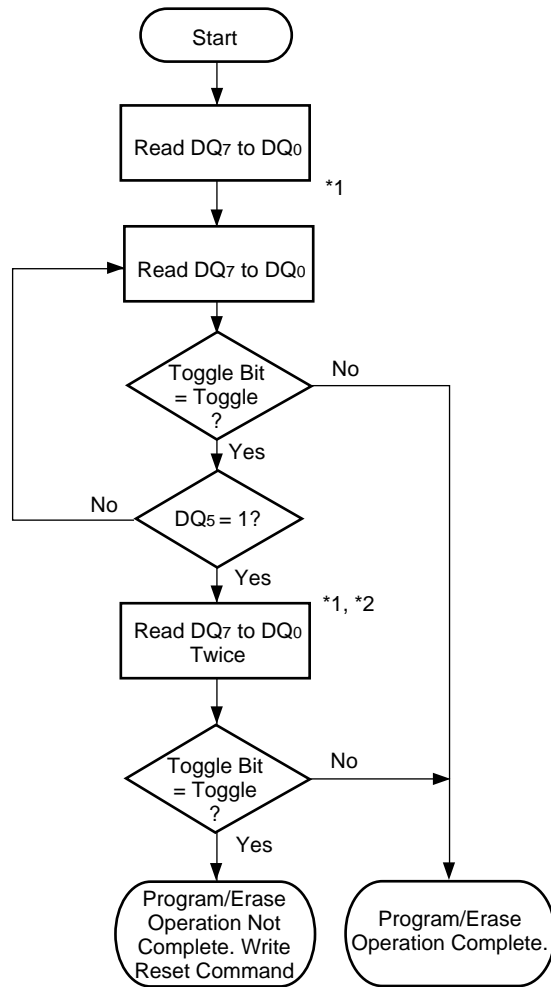


Figure 18 Embedded Erase™ Algorithm



*: DQ₇ is rechecked even if DQ₅ = "1" because DQ₇ may change simultaneously with DQ₅.

Figure 19 Data Polling Algorithm



*1: Reset toggle bit twice to determine whether or not it is toggle.

*2: Recheck toggle bit because it may stop toggle as DQ₅ changes to "1".

Figure 20 Toggle Bit Algorithm

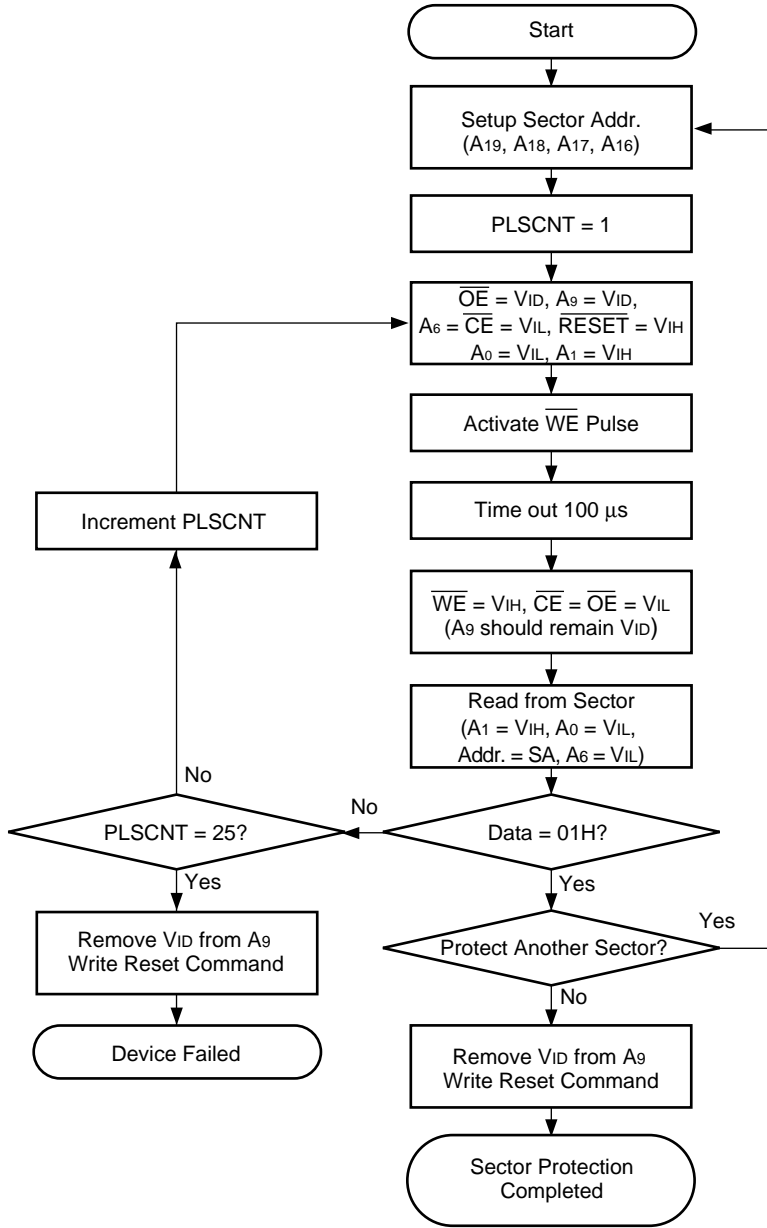
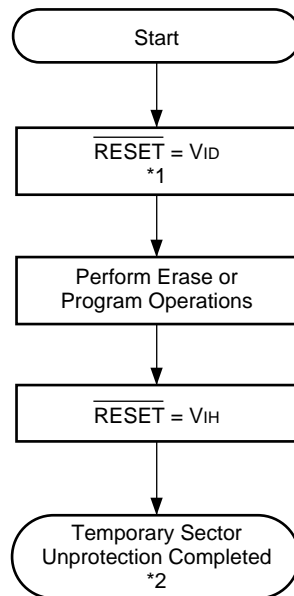


Figure 21 Sector Protection Algorithm



*1: All protected sectors are unprotected.

*2: All previously protected sectors are protected once again.

Figure 22 Temporary Sector Unprotection Algorithm

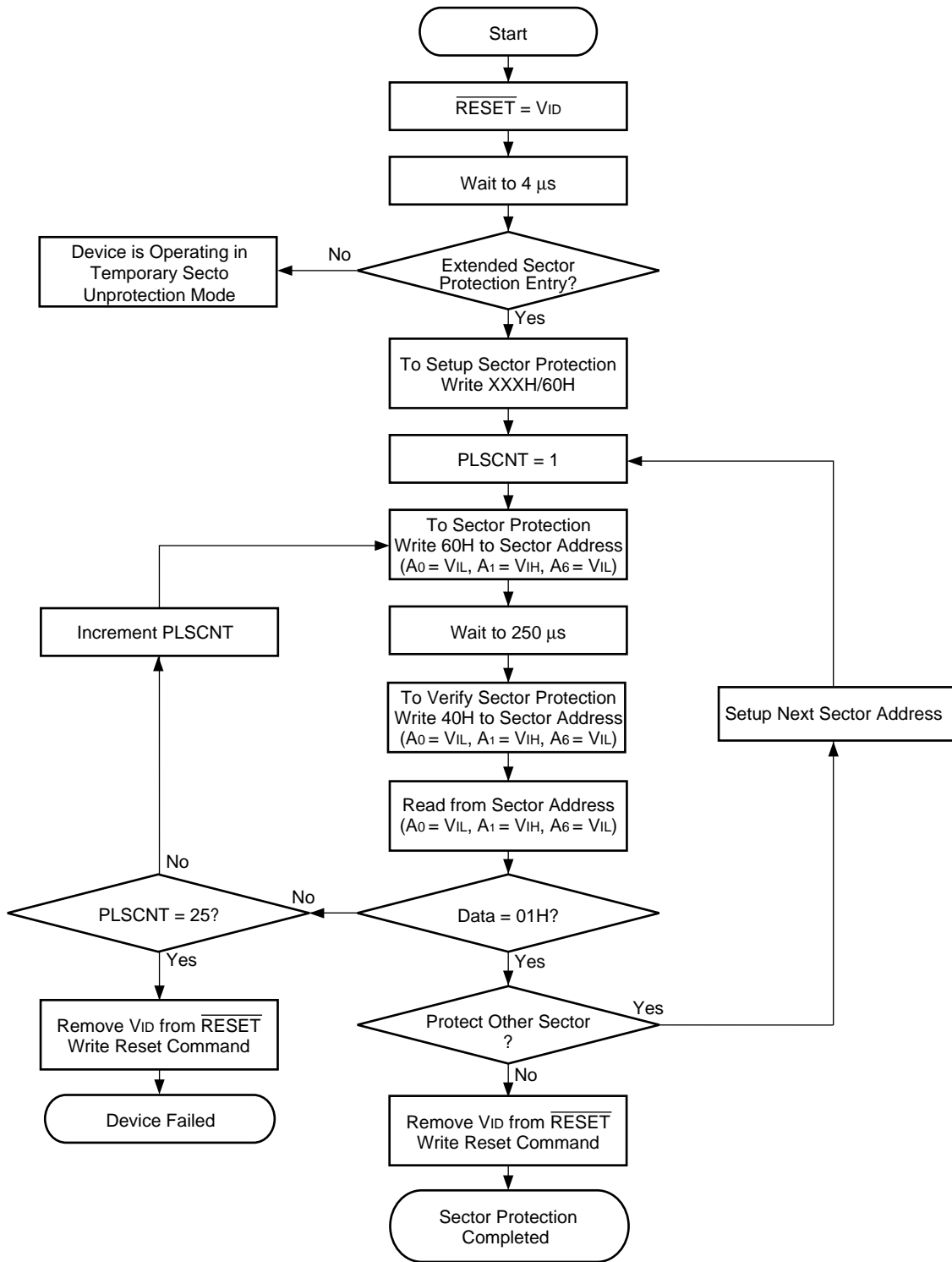


Figure 23 Extended Sector Protection Algorithm

FAST MODE ALGORITHM

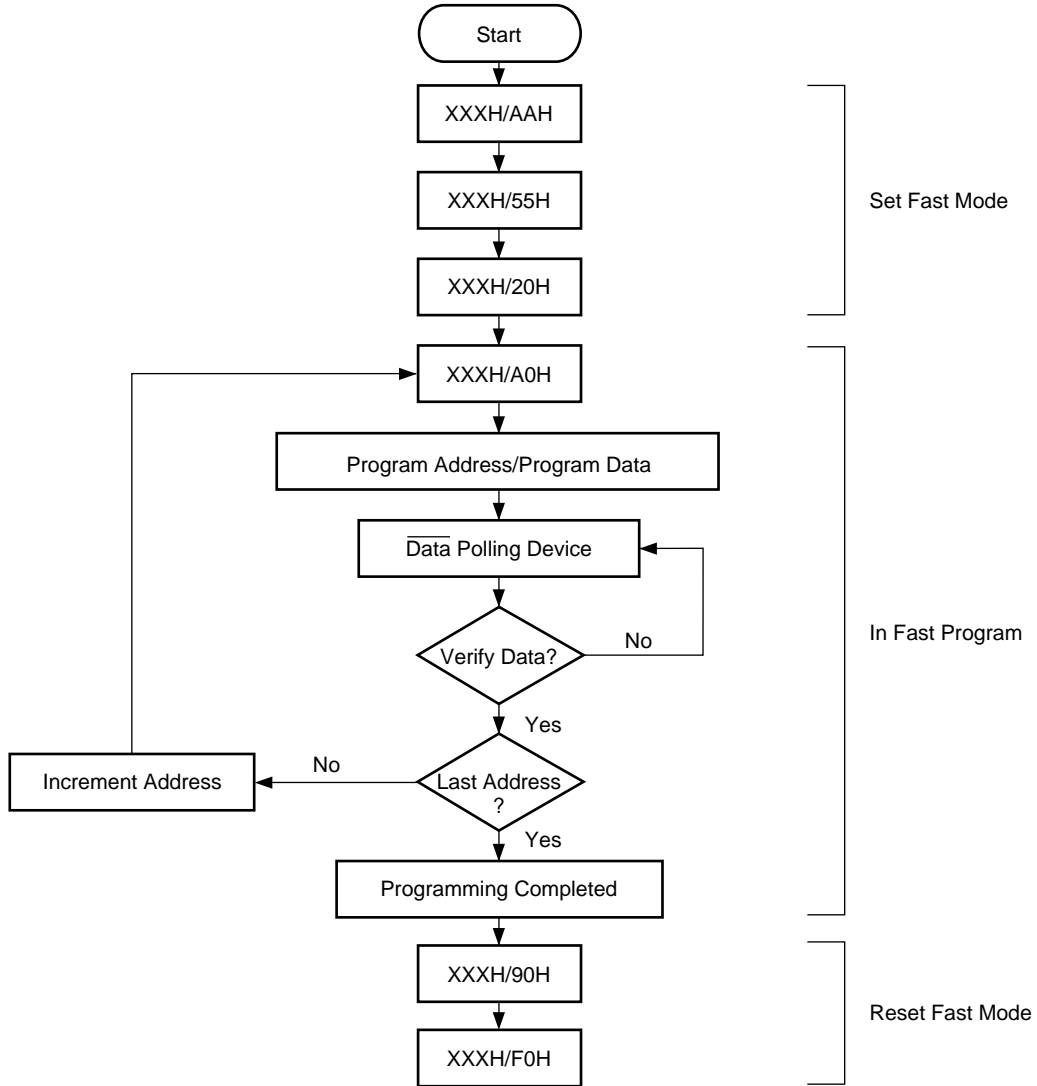


Figure 24 Embedded Program™ Algorithm for Fast Mode

■ ERASE AND PROGRAMMING PERFORMANCE

Parameter	Limits			Unit	Comments
	Min.	Typ.	Max.		
Sector Erase Time	—	1	10	s	Excludes programming time prior to erasure
Byte Programming Time	—	8	300	μs	Excludes system-level overhead
Chip Programming Time	—	8.4	25	s	Excludes system-level overhead
Erase/Program Cycle	100,000	—	—	cycle	—

■ TSOP (I) PIN CAPACITANCE

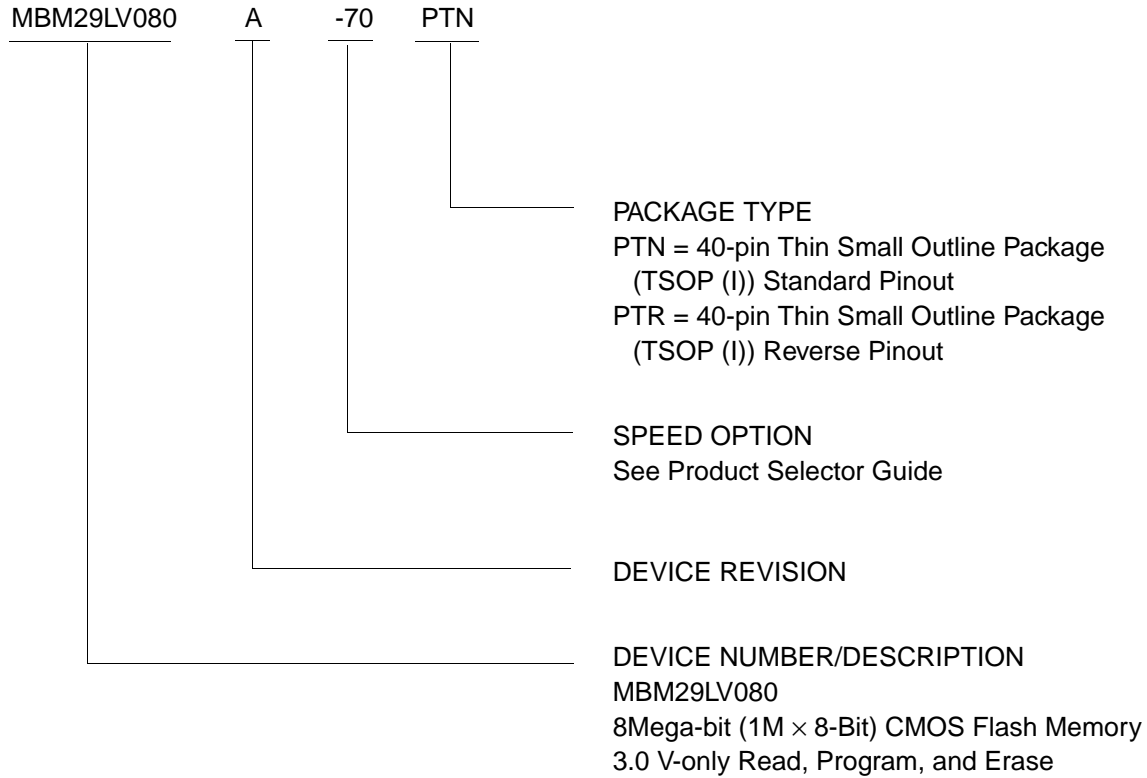
Parameter Symbol	Parameter Description	Test Setup	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0	7	10	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0	8	10	pF
C _{IN2}	Control Pin Capacitance	V _{IN} = 0	10	12.5	pF

Note: Test conditions T_A = 25°C, f = 1.0 MHz

■ ORDERING INFORMATION

Standard Products

Fujitsu standard products are available in several packages. The order number is formed by a combination of:

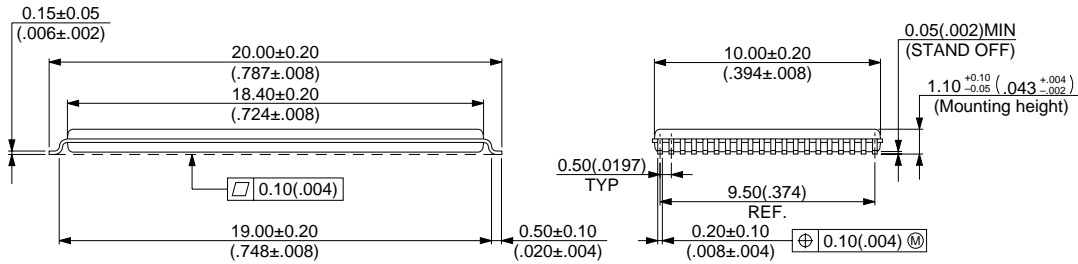
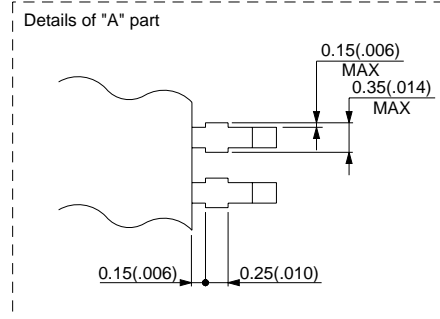
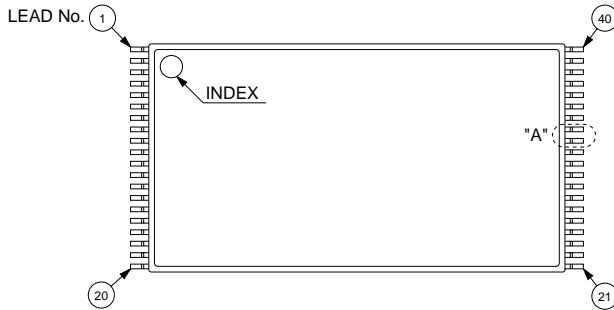


Part number	Package	Remarks
MBM29LV080A-70PTV MBM29LV080A-90PTV MBM29LV080A-12PTV	40-pin plastic TSOP(I) (FPT-40P-M06) Standard Pinout	
MBM29LV080A-70PTR MBM29LV080A-90PTR MBM29LV080A-12PTR	40-pin plastic TSOP(I) (FPT-40P-M07) Reverse Pinout	

MBM29LV080A-70/-90/-12

PACKAGE DIMENSIONS

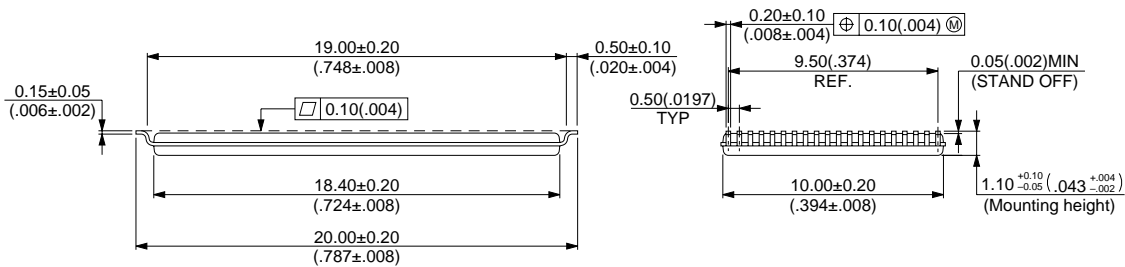
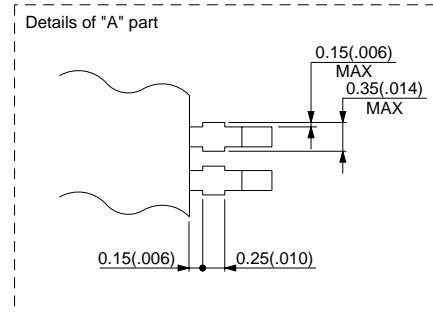
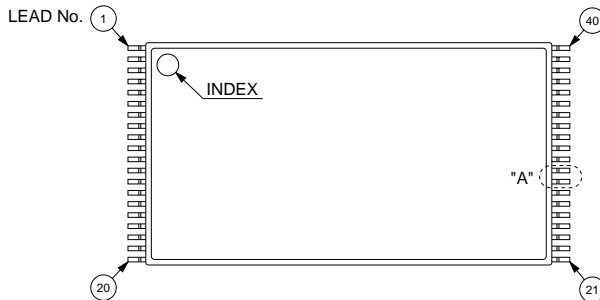
40-pin plastic TSOP(I)
(FPT-40P-M06)



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Dimensions in mm (inches).

40-pin plastic TSOP(I)
(FPT-40P-M07)



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Dimensions in mm (inches).

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